

Description

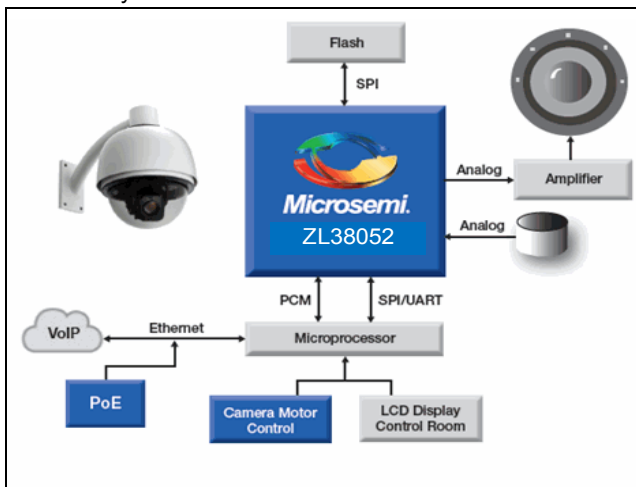
The ZL38052 is part of Microsemi's Timberwolf audio processor family of products. These devices feature Microsemi's innovative *AcuEdge* acoustic technology, which is a set of highly-complex and integrated algorithms. The Microsemi *AcuEdge* Technology ZL38052 is designed to provide leading edge far field microphone processing with advanced features targeted for IP and security cameras with high definition (HD) 2-way hands-free voice.

The Microsemi *AcuEdge* Technology license-free, royalty-free intelligent audio Firmware provides Beamforming, Sound Location Estimation, Acoustic Echo Cancellation (AEC), Noise Reduction and a variety of other voice enhancements to improve both the intelligibility and subjective quality of voice in harsh environments. The ZL38052 also incorporates a sound classification feature allowing the system to recognize smoke detector alarms (T3), carbon monoxide detector alarms (T4) and glass break detection.

Microsemi offers additional tools to speed up the product development cycle. The *MiTuner*™ ZLS38508 or ZLS38508LITE GUI software packages allow a user to interactively configure the ZL38052 device. The optional *MiTuner* ZLE38470BADA Automatic Tuning Kit provides automatic tuning and easy control for manual fine tuning adjustments.

Applications

- IP Cameras
- Security Cameras



Typical IP Security Camera Application

Document ID# 154531

Version 1

March 2016

Ordering Information

Device OPN	Package	Packing
ZL38052LDF1	64-pin QFN (9x9)	Tape & Reel
ZL38052LDG1	64-pin QFN (9x9)	Tray
ZL38052UGB2	56-ball WLCSP (3.1x3.1)	Tape & Reel

These packages meet RoHS 2 Directive 2011/65/EU of the European Council to minimize the environmental impact of electrical equipment.

Microsemi *AcuEdge* Technology ZLS38052 Firmware

There are two Firmware images that may be selected to provide the desired operating mode. Firmware images can be swapped during normal operation to switch modes dynamically. Firmware image size varies with firmware load.

ZLS38052.0 (Full Duplex Communication)

- Far Field Microphone Processing
- Microphone Beamforming
- Sound Location Estimation
- Full Narrowband and Wideband Acoustic Echo cancellation operation
 - Supports long tail AEC (up to 256 ms)
 - Non-Linear AEC provides higher tolerance for speaker distortions
- Howling detection/cancellation
 - Prevents oscillation in AEC audio path
- Advanced noise reduction reduces background noise from the near-end speech signal using Psychoacoustic techniques
- Various encoding/decoding options: 16-bit linear, G.722, G.711 A/μlaw
- Send and receive path equalizers

ZLS38052.2 (Glass Break and Energy Detectors)

- Detects T3 (Temporal smoke alarm) signals
- Detects T4 (Temporal carbon monoxide alarm) signals
- Detects the sound of breaking glass
- Programmable Energy Detector

ZL38052 Hardware Features

- DSP with Voice Hardware Accelerators

- 2 digital microphone interfaces allowing sampling of up to 4 digital Microphones
- 2 independent headphone drivers
 - Dual 16-bit digital-to-analog converters (DACs)
 - 16 ohms single-ended or differential drive capability
 - 32 mW output drive power into 16 ohms
- 2 Time-Division Multiplexing (TDM) buses
 - The ports can be configured for Inter-IC Sound (I²S) or Pulse-Code Modulation (PCM) operation
 - PCM operation supports PCM and GCI timing, I²S operation supports I²S and left justified timing
 - Each port can be a clock master or a slave
 - Each port supports up to four bi-directional streams when configured in PCM mode or two bi-directional streams when configured for I²S mode at data rates from 128 kb/s to 8 Mb/s
- 2 Serial Peripheral Interface (SPI) ports
 - The SPI Slave port is recommended as the main communication port with a host processor. The port provides the fastest means to Host Boot and configures the device's firmware and configuration record.
 - The Master SPI port is used to load the device's firmware and configuration record from external Flash memory (Auto Boot).
- Inter-Integrated Circuit (I²C) Port (pins shared with SPI Slave Port)
 - The I²C port can be used as the main communication port with a host processor, and can be used to Host Boot and configure the device's firmware and configuration record
- General purpose Universal Asynchronous Receiver/Transmitter (UART) port for debug
 - The UART port can be used as a debug tool and is used for tuning purposes
- 14 General Purpose Input/Output (GPIO) pins (full operation with Full Duplex Communication Firmware, limited operation with Alarm, Glass Break And Energy Detector Firmware)
 - GPIO ports can be used for interrupt and event reporting, fixed function control, bootstrap

options, as well as being used for general purpose I/O for communication and controlling external devices

The *MiTuner*™ Automatic Tuning Kit and ZLS38508 *MiTuner* GUI

Microsemi's Automatic Tuning Kit option includes:

- Audio Interface Box hardware
- Microphone and Speaker
- ZLS38508 *MiTuner* GUI software
 - Allows tuning of Microsemi's *AcuEdge* Technology Audio Processor

The ZLS38508 software features:

- Auto Tuning and Subjective Tuning support
- Allows tuning of key parameters of the system design
- Provides visual representations of the audio paths with drop-down menus to program parameters, allowing:
 - Control of the audio routing configuration
 - Programming of key building blocks in the transmit (Tx) and receive (Rx) audio paths
 - Setting analog and digital gains
- Configuration parameters allow users to “fine tune” the overall performance



Tools

- ZLK38000 Evaluation Kit
- *MiTuner*™ ZLS38508 and ZLS38508LITE GUI
- *MiTuner*™ ZLE38470BADA Automatic Tuning Kit

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1.0 ZL38052 Device Overview

The Microsemi ZL38052 Audio Processor powered by ZLS38052 *AcuEdge*™ Technology Firmware is ideal for providing high definition audio to IP cameras. The ZL38052 has two primary modes of operation 1) Full Duplex Communication mode and 2) Sound Classifier mode.

In general, the two modes of operation provide the following functionality:

Full Duplex Communication Mode

This mode offers a high performance two way audio solution offering the following features:

- Wide band (16 kHz sampling) operation
- Configurable Acoustic Echo Canceler (AEC)
 - Programmable echo cancellation tail length up to 256 ms
 - Non-linear Acoustic Echo Controller
 - Non-Linear Processor (NLP)
- Beamforming with two or three microphone array
- Sound Locator identifies the direction of the loudest audio source, providing alerts of potential interest
- Patented Psycho-Acoustic Noise Reduction – up to 20 dB for white noise
- Integrated Compressor / Limiter / Expander enhances intelligible speech from significant distances
- Patented Anti-Howling – reduces oscillation in echo canceller audio path, including co-located devices
- Parametric Equalizers in the Send and Receive paths
- Programmable Tone Generators to generate DTMF, tone ringer, and test tones
- Cross Point Switch provides signal mixing
- Programmable coding (μ /A-law ITU-T G.711, G.722, or 16- bit linear) at line interface

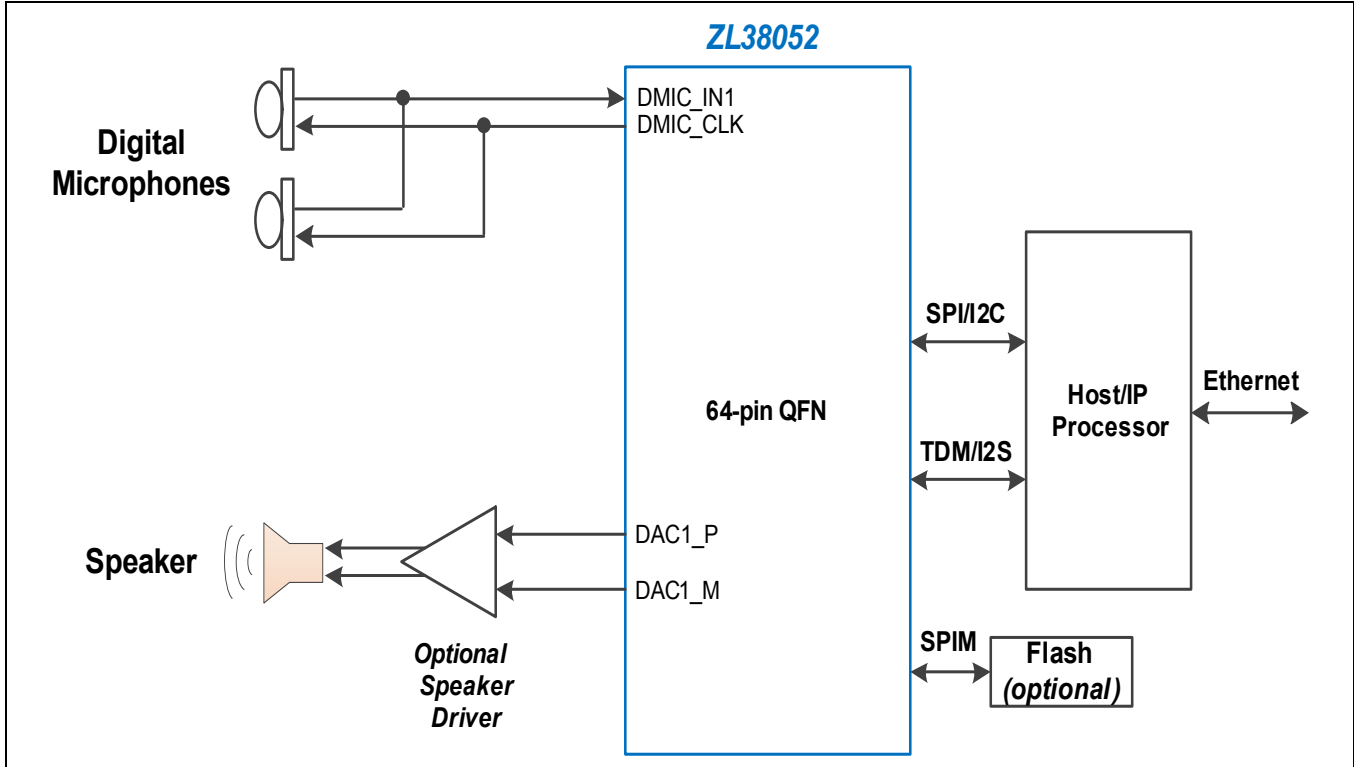
Sound Classifier Mode

The mode offers a sound classification feature with the following features:

- Smoke detector alarm (T3)
- Carbon monoxide alarms (T4)
- Glass break detector
- Programmable Energy Detector

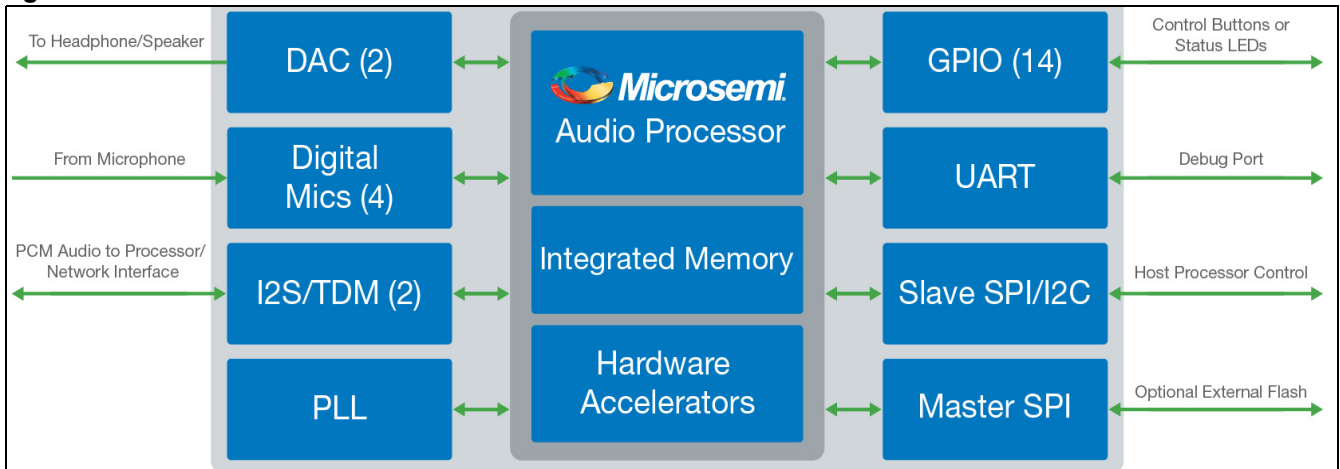
A typical IP Camera application is presented in [Figure 1](#).

Figure 1 - IP Camera HD Voice Full Duplex Communication Application



The main functional blocks of the ZL38052 device are shown in [Figure 2](#).

Figure 2 - ZL38052 Audio Processor for IP Cameras



2.0 Firmware

The two modes of operation in the ZL38052 (Full Duplex Communication and Sound Classification) are selected depending on which Firmware is loaded into the device. The Firmware is initially loaded at power up, either from external serial Flash or from a host controller (see [7.0, "Device Booting and Firmware Swapping" on page 31](#)). Real time switching between the two Firmware modes can be done during normal operation, however this requires a host controller to support. There are timing constraints that should be noted for Firmware Swapping (see [11.2, "Host Bus Interface Timing Parameters" on page 55](#) for more information).

The ZL38052 Firmware Manual provides detailed information on the use of the two firmware modes of operation for the ZL38052 and should be consulted.

The majority of the signal processing (AEC, Equalization, Noise Reduction, Beamforming, CLE, etc.) runs in the Audio Processor Block at 16 kHz. Each of the audio inputs (Digital Mics, I²S/TDM) and outputs (DACs, I²S/TDM) can be routed amongst themselves or to the Audio Processor via a highly configurable Cross Point Switch.

The ZL38052 device provides the following peripheral interfaces:

- 2 digital microphone interfaces allowing sampling of up to 4 digital microphones
- 2 Time-Division Multiplexing (TDM) buses
 - The ports can be configured for Inter-IC Sound (I²S) or Pulse-Code Modulation (PCM) operation
 - PCM operation supports PCM and GCI timing, I²S operation supports I²S and left justified timing
 - Each port can be a clock master or a slave
 - Each port supports up to four bi-directional streams when configured in PCM mode or two bi-directional streams when configured for I²S mode at data rates from 128 kb/s to 8 Mb/s
 - Sample rate conversions are automatically done when data is sent/received at different rates than is processed internally
- SPI – The device provides two Serial Peripheral Interface (SPI) ports
 - The SPI Slave port is recommended as the main communication port with a host processor. The port provides the fastest means to Host Boot and configure the device's firmware and configuration record*.
 - The Master SPI port is used to load the device's firmware and configuration record from external Flash memory (Auto Boot).
- I²C - The device provides one Inter-Integrated Circuit (I²C) port. (pins are shared with the SPI Slave port)
 - The I²C port can be used as the main communication port with a host processor, and can be used to Host Boot and configure the device's firmware and configuration record.
- UART – The device provides one Universal Asynchronous Receiver/Transmitter (UART) port
 - The UART port can be used as a debug tool and is used for tuning purposes.
- GPIO – The device provides 14 General Purpose Input/Output (GPIO) ports (full operation with Full Duplex Communication Firmware, limited operation with Alarm, Glass Break And Energy Detector Firmware).
 - GPIO ports can be used for interrupt and event reporting, fixed function control, bootstrap options, as well as being used for general purpose I/O for communication and controlling external devices.
 - The 56 pin WLCSP package is limited to 11 GPIOs.

* Note: The configuration record is a set of register values that are customizable by the application developer to configure and tune the ZL38052 for a particular design. Refer to the Microsemi AcuEdge™ Technology ZLS38052 Firmware Manual for firmware and configuration record information.

2.1 Full Duplex Communication Mode (Firmware ZLS38052.0)

The ZLS38052.0 Firmware offers a sophisticated audio compressor/limiter/expander (CLE) with adjustable attack and decay time. This feature along with Beamforming and advanced Noise Reduction allows for Far Field Microphone pick-up.

The full duplex communication firmware (ZLS38052.0) supports the following additional ports:

- 2 independent headphone drivers
 - Dual 16-bit digital-to-analog converters (DACs)
 - 16 ohms single-ended or differential drive capability

- 32 mW output drive power into 16 ohms

2.2 Sound Classifier Mode (Firmware ZLS38052.2)

This mode of operation uses a single microphone input to be able to provide enhanced Sound Classification. This mode of operation supports:

- Detects T3 (temporal smoke alarm) signals
- Detects T4 (temporal carbon monoxide alarm) signals
- Detects the sound of breaking glass
- Programmable Energy Detector

Refer to the *Microsemi AcuEdge™ Technology ZLS38052 Firmware Manual* for more information on the Firmware options and usage for the ZL38052.

3.0 Audio Interfaces

3.1 Digital Microphone Interface

The ZL38052 supports up to four digital microphones using the DMIC_CLK, DMIC_IN1, and DMIC_IN2 interface pins.

The ZL38052 digital microphone clock output (DMIC_CLK) is either 1.024 MHz or 3.072 MHz depending on the selected TDM-A sample rate. Selecting 16 kHz TDM-A sample rate corresponds to a 1.024 MHz digital microphone clock and selecting a 48 kHz sample rate corresponds to a 3.072 MHz digital microphone clock. Microphone data is decimated and filtered to operate at 16 kHz sampling rate of the Audio Processing block. When there is no TDM-A bus to set the sample rate, the ZL38052 will operate from the crystal (or clock oscillator) and will pass digital audio from the microphones operating at a 48 kHz sampling rate.

When in full duplex communication mode, AEC can be performed on up to three microphones selected to go to the ZL38052 voice processing section, the other paths may be routed to the TDM bus for use by the host or an external Codec. Alternatively the host processor can switch different microphones to the voice processing inputs. Note that when in sound classification mode, only one microphone is used/required. It runs at 1.024 MHz sampling rate.

A stereo digital microphone, or two separate mono digital microphones, can send two microphone channels on one pin by sending the data for one channel on the rising edge and one channel on the falling edge. The selection for which clock edge is used to clock in the microphone data (rising/falling) is done via the Microphone Enable Configuration register (host writable over the HBI) or in the configuration record (loaded from Flash). Various digital microphone interfaces are presented in [Figures 3 - 5](#).

An electret condenser microphone can be used with the digital microphone input by using a Digital Electret Microphone Pre-Amplifier device as shown in [Figure 6](#).

Beamforming can be performed with 2 or 3 microphones. The Beamformer uses the signals from multiple microphones to determine the direction of arrival of various sound sources. The Beamformer accepts those sources that it determines are in the direction of interest and attenuates those that are deemed to be coming from other directions. By attenuating anything outside of the beam, the distance of microphone pick-up improves and interfering sounds are reduced. The Beamformer's beam width, steering angle, and out-of-beam attenuation are programmable. The physical spacing between microphones is important when implementing Beamforming. Beamforming with two microphones is most optimal when the microphones are spaced 50mm to 60mm apart. When using three microphones, the optimal spacing is 30mm apart. The microphones must also be oriented along the same plane and face the same direction. Please consult with Microsemi applications support for more information when optimizing the design for Beamforming.

In addition to Beamforming, the Microsemi *AcuEdge™* Technology Sound Location feature reports the angle at which a sound arrives at the microphone array (2 or 3 microphones).

Figure 3 - Single Mono Digital Microphone Interface – Full Duplex Communications Mode or Sound Classification Mode

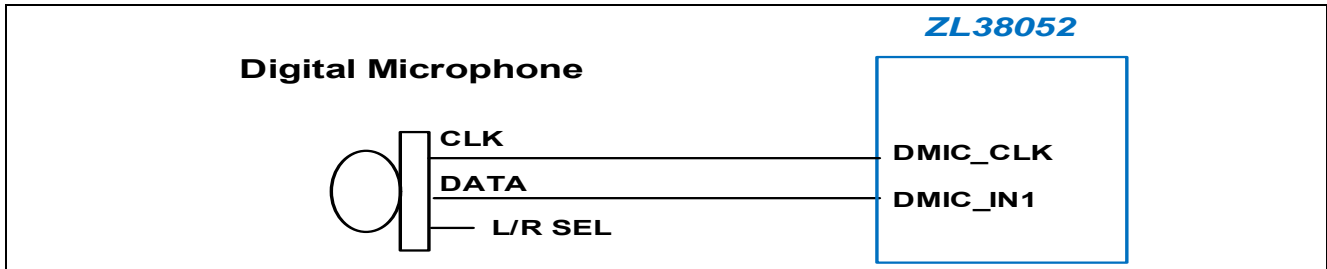


Figure 4 - Dual Microphone or Stereo Digital Microphone Interface – Full Duplex Communications Mode

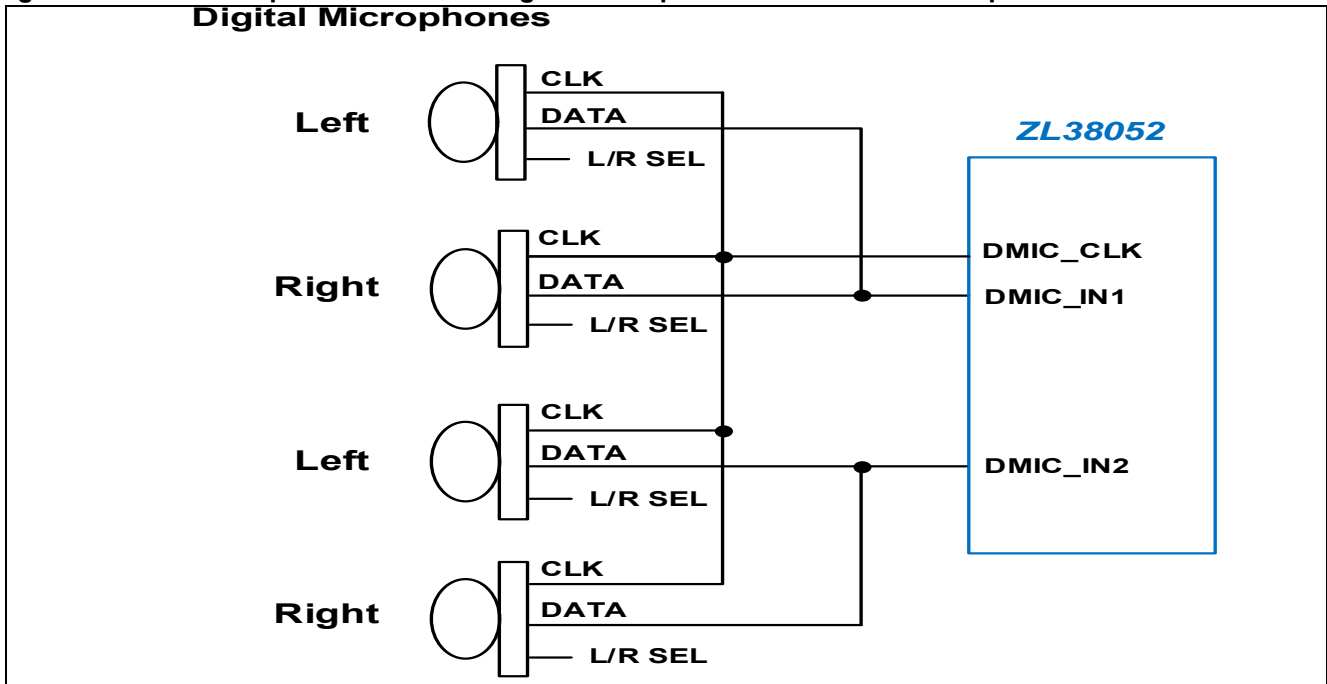
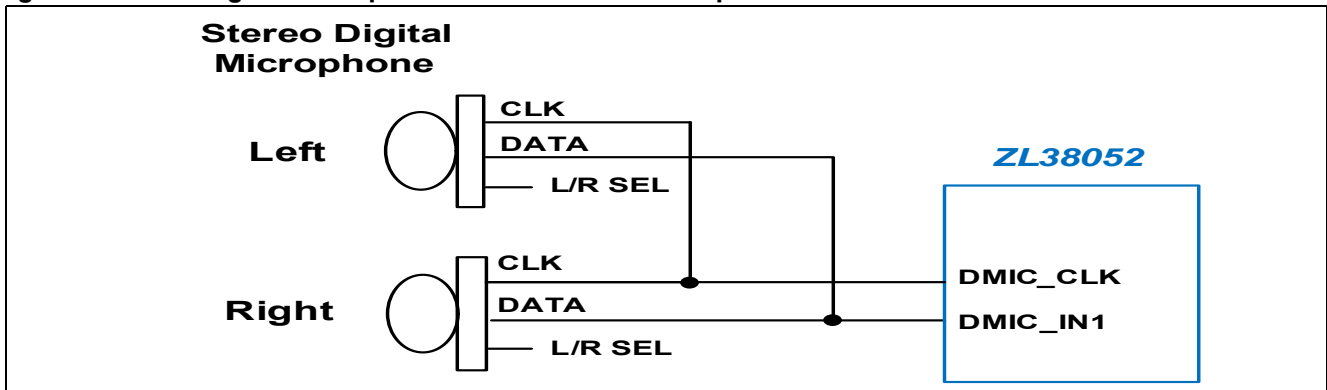


Figure 5 - Four Digital Microphone Interfaces – Full Duplex Communications Mode



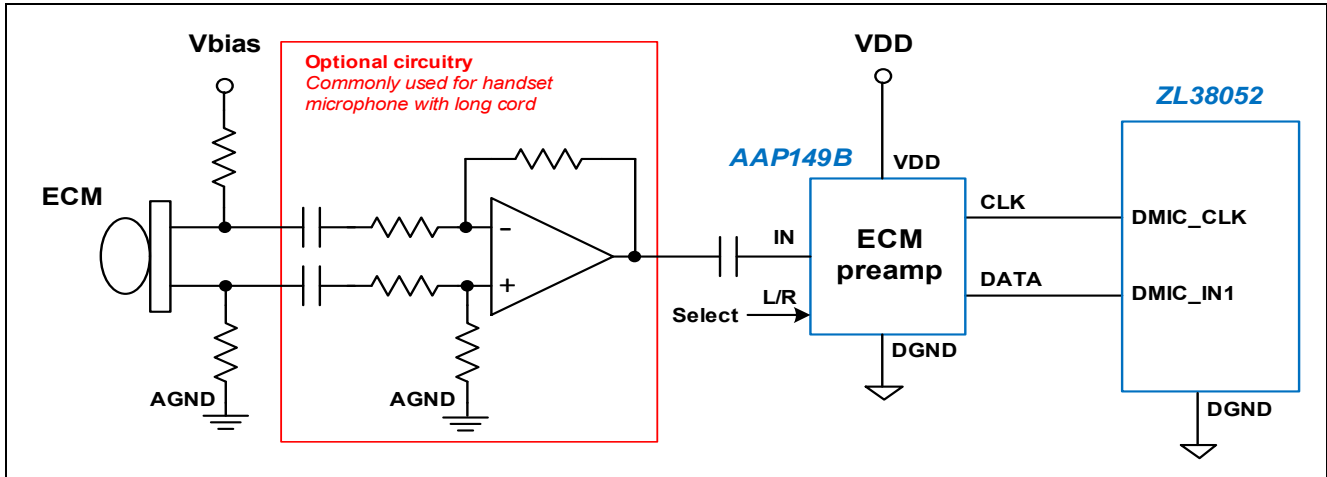
3.1.1 Analog Microphone Use

To use analog electret condenser microphones (ECM) with the digital microphone interface, a Digital Electret Microphone Pre-Amplifier device is required. [Figure 6](#) illustrates an analog microphone connection.

The analog microphone is wired to an optional differential amplifier which amplifies and converts the microphone signal to single-ended. The microphone signals are then further amplified and digitized through the Digital Electret Microphone Pre-Amplifiers and applied to the ZL38052 digital microphone input. A Microsemi AAP149B ECM Pre-Amplifier is shown.

The ZL38052 provides the clock to activate the Digital Electret Microphone Pre-Amplifier.

Figure 6 - ECM Circuit



When using an analog microphone, operation in Low-Power mode is not recommended. For more information, see [10.4, "Device Operating Modes" on page 43](#).

3.2 DAC Output

The ZL38052 has two 16-bit fully differential delta-sigma digital-to-analog converters. The two output DACs independently drive an analog output subsystem. Each subsystem is able to drive two output pins, representing four independent single-ended headphone outputs that can be driven by two independent data streams. The pins can be independently configured. Four analog gains on each headphone output are provided and can be set to: 1x, 0.5x, 0.333x, or 0.25x.

Note: Only the positive DAC outputs are available with the 56-ball WLCSP package. The 56-ball WLCSP package provides two independent single-ended headphone outputs that can be driven by two independent data streams.

The headphone amplifiers are self-protecting so that a direct short from the output to ground or a direct short across the terminals does not damage the device.

The ZL38052 provides audible pop suppression which reduces pop noise in the headphone earpiece when the device is powered on/off or when the device channel configurations are changed. This is especially important when driving a headphone single-ended through an external capacitor (see [3.2.2, "Output Driver Configurations", configuration C](#)).

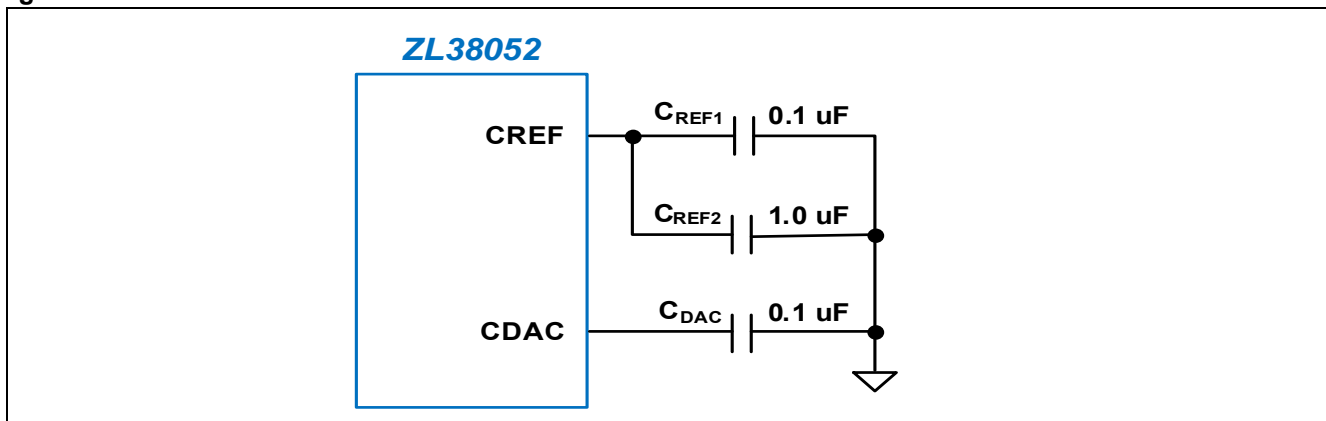
The DACs and headphone amplifiers can be powered down if they are not required for a given application. To fully power down the DACs, disable both the positive and negative outputs.

3.2.1 DAC Bias Circuit

The common mode bias voltage output signal (CREF) for the DAC output buffers must be decoupled through a 0.1 μF (C_{REF1}) and a 1.0 μF (C_{REF2}) ceramic capacitor to VSS. The positive DAC reference voltage output (CDAC) must be decoupled through a 0.1 μF (C_{DAC}) ceramic capacitor to VSS as shown in [Figure 7](#).

All capacitors can have a 20% tolerance and should have a minimum voltage rating of 6.3 V.

Figure 7 - ZL38052 Bias Circuit



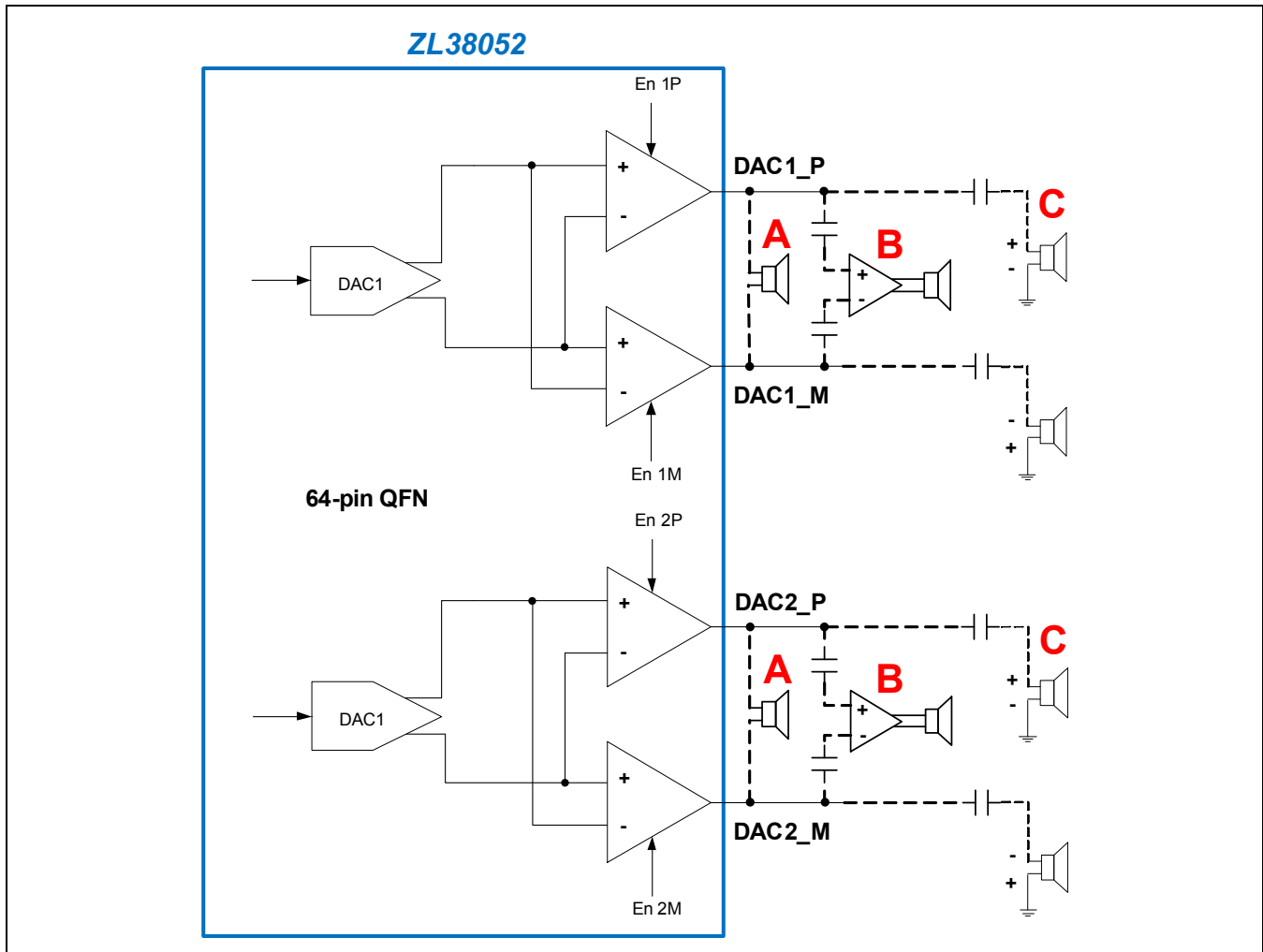
3.2.2 Output Driver Configurations

[Figure 8](#) shows the different possible output driver configurations for the 64-pin QFN package. When using the 56-ball WLCSP package, only the positive outputs DAC1_P and DAC2_P are provided.

The two output DACs independently drive positive and negative headphone driver amplifiers. The output pins can be independently configured in the following ways:

- A. 64-pin QFN – Direct differential drive of a speaker as low as 32 ohms. For this configuration an analog gain of 1x is commonly used. (Differentially driving a 16 ohm speaker is possible, but only with the same amount of power as in the single-ended case. The signal level must be reduced to not exceed $\frac{1}{2}$ scale in this case.)
- B. 64-pin QFN – Direct differential drive of a high impedance power amplifier. A Class D amplifier is recommended for this speaker driver. Use an ON Semiconductor[®] NCP2820 or equivalent. A 1 μ F coupling capacitor is generally used with the Class D amplifier. The analog gain setting depends on the gain of the Class D amplifier, analog gain settings of 0.25x or 0.5x are commonly used.
- C. Both packages – Driving either a high impedance or a capacitively coupled speaker as low as 16 ohms single-ended. For this configuration an analog gain of 1x is commonly used. The coupling capacitor value can vary from 10 μ f to 100 μ f depending on the type of earpiece used and the frequency response desired.

Figure 8 - Audio Output Configurations



4.0 Digital Interfaces

4.1 TDM Interface

The ZL38052 device has two generic TDM interfaces, TDM-A and TDM-B. Each interface consists of four signals:

- Data clock (PCLK/I2S_SCK)
- Data rate sync (FS/I2S_WS)
- Serial data input (DR/I2S_SDI)
- Serial data output (DX/I2S_SDO)

The TDM ports can be configured for Inter-IC Sound (I²S) or Pulse-Code Modulation (PCM) operation.

Each TDM block is capable of being a master or a slave, however both highways must be synchronous to each other (derived from a common clock domain).

Operation of the TDM interfaces are subject to the following limitations.

Table 1 - Allowable TDM Configurations

TDM-A Mode	TDM-B Mode	Supported Sample Rates ³ (kHz)	Requirements / Limitations
Master	Master	8, 16, 48	Both TDM-A and TDM-B must be configured for the same data clock and data sync.
Master	Slave-Synchronous		The TDM-B sync rate must either be the same as the TDM-A sync rate or 48 kHz.
Slave ¹	Master		
Slave ¹	Slave-Synchronous ²		

Note 1: When TDM-A is a slave, then the device can be run without a crystal. However, this mode requires that the PCLKA and FSA signals are always present and PCLKA must be an integer multiple of 2.048 MHz. For crystal-less operation at power-on, PCLKA will be auto-detected with only 8 kHz and 16 kHz frame syncs being allowed.

Note 2: This combination requires that both TDM-A clock and TDM-B clock be physically connected to the same source.

Note 3: The Audio Processing block accepts these sample rates but the Audio Processing block always runs at a 16 kHz sampling rate.

While a TDM bus configuration may carry many encoded audio streams, the ZL38052 device can only address a maximum of 4 bi-directional audio streams per TDM bus. These four audio streams are referred to as channels #1 through #4, and each of these channels can be independently configured to decode any of the TDM bus's audio streams.

For a given TDM bus, once it is configured for a data sample rate and encoding, all data rates and encoding on that bus will be the same. 16-bit linear data will be sent on consecutive 8-bit timeslots (e.g., if timeslot N is programmed in the timeslot registers, the consecutive timeslot is N+1).

The TDM interface supports bit reversal (LSB first \leftrightarrow MSB first) and loopbacks within the TDM interface and from one interface to another (see [“Cross Point Switch” on page 21](#)).

The generic TDM interface supports the following mode and timing options.

4.1.1 I²S Mode

In I²S mode, the 4-wire TDM port conforms to the I²S protocol and the port pins become I2S_SCK, I2S_WS, I2S_SDI, and I2S_SDO (refer to [Table 10](#) for pin definitions). Both TDM buses have I²S capability.

An I²S bus supports two bi-directional data streams, left and right channel, by using the send and receive data pins utilizing the common clock and word signals. The send data is transmitted on the I2S_SDO line and the receive data is received on the I2S_SDI line.

The I²S port can be used to connect external analog-to-digital converters or Codecs. The port can operate in master mode where the ZL38052 is the source of the port clocks, or slave mode where the word select and serial clocks are inputs to the ZL38052.

The word select (I2S_WS) defines the I²S data rate and sets the frame period when data is transmitted for the left and right channels. A frame consists of one left and one right audio channel. The I²S ports operate at 8, 16, and 48 kHz data rates as a slave or master (as specified in [Table 1](#)). Per the I²S standard, the word select is output using a 50% duty cycle.

The serial clock (I2S_SCK) rate sets the number of bits per word select frame period and defines the frequency of I2S_CLK. I²S data is input and output at the serial clock rate. Input data bits are received on I2S_SDI and output data bits are transmitted on I2S_SDO. Data bits are always MSB first. The number of clock and data bits per frame can be programmed as 8, 16, 32, 64, 96, 128, 192, 256, 384, 512, or 1024. Any input data bits that are received after the LSB are ignored.

The I²S port operates in two frame alignment modes (I²S and Left justified) which determine the data start in relation to the word select.

Figure 9 illustrates the I²S mode, which is left channel first with I2S_WS (Left/Right Clock signal) low, followed by the right channel with I2S_WS high. The MSB of the data is clocked out starting on the second falling edge of I2S_SCK following the I2S_WS transition and clocked in starting on the second rising edge of I2S_SCK following the I2S_WS transition. Figure 9 shows I²S operation with 32 bits per frame.

Figure 9 - I²S Mode

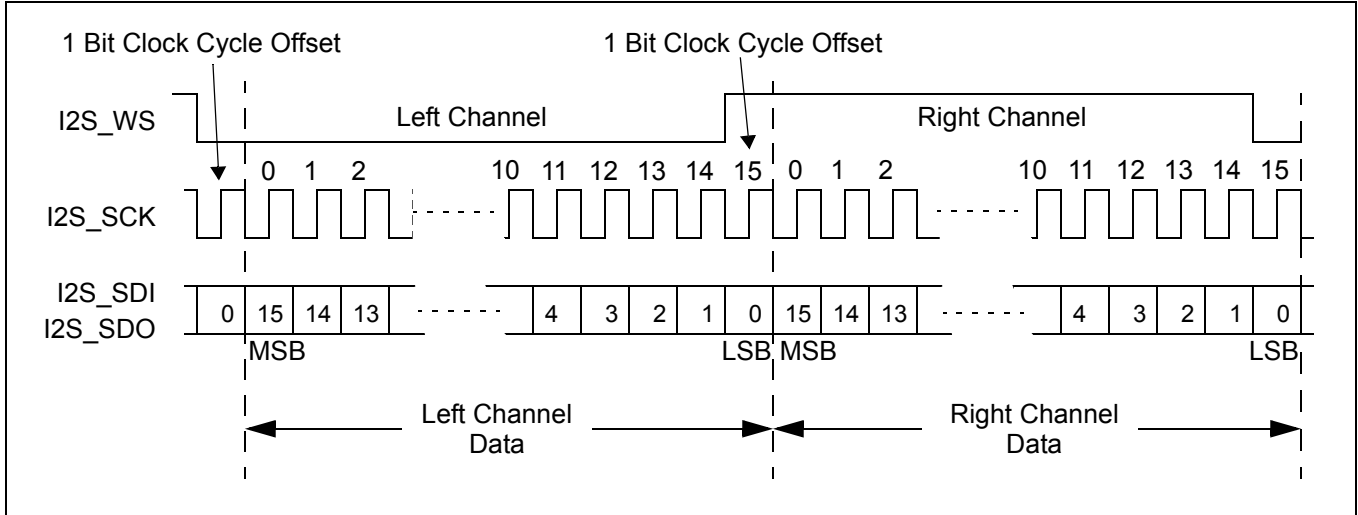
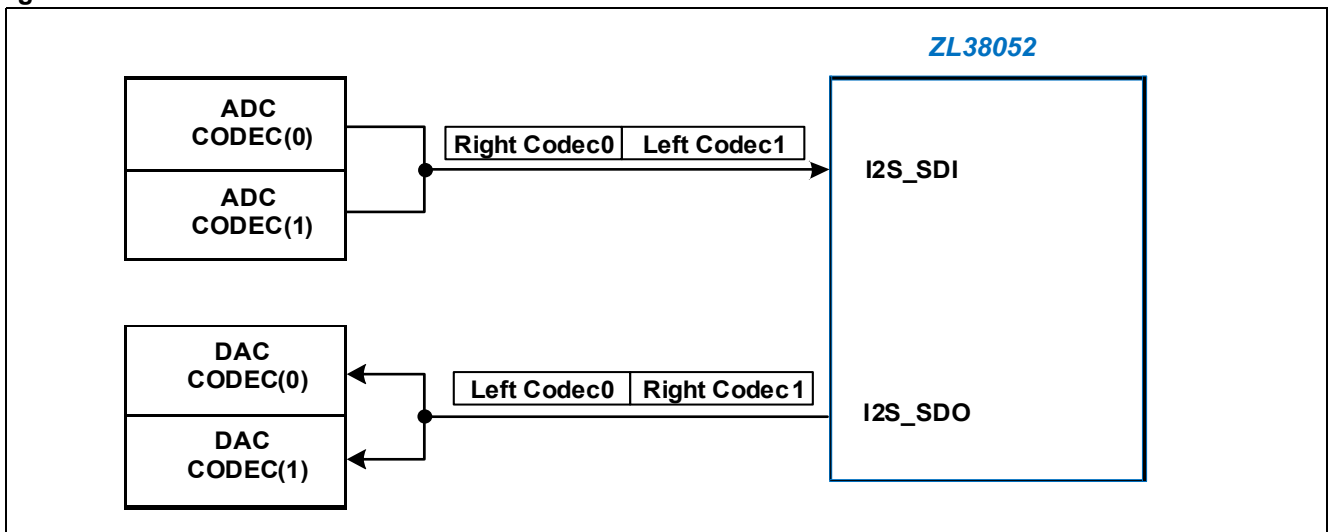


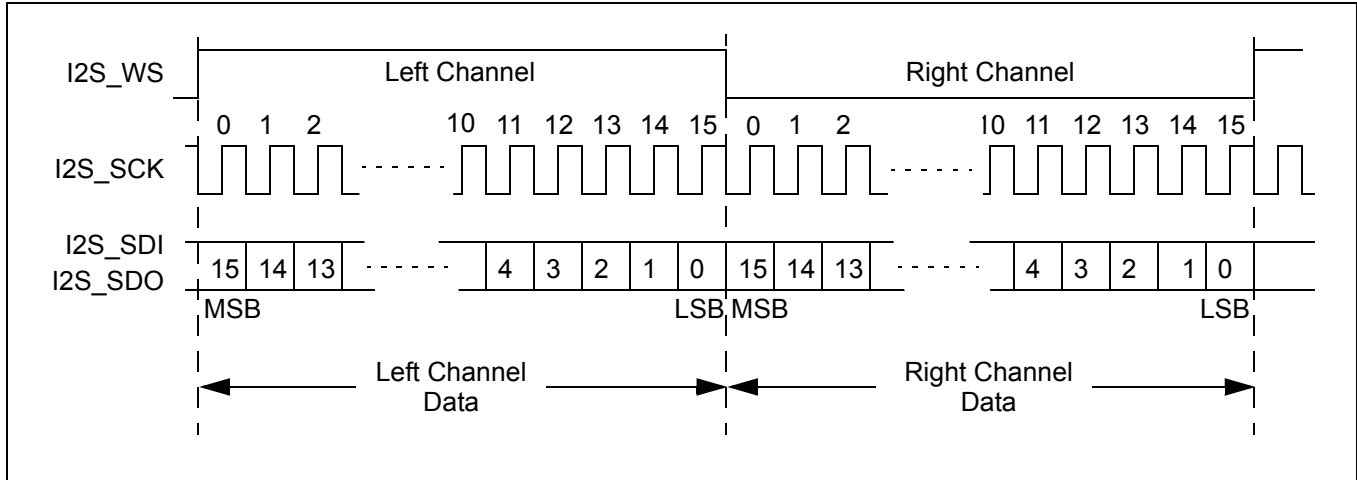
Figure 10 illustrates the left justified mode, which is left channel first associated with I2S_WS (Left/Right Clock signal) high, followed by the right channel associated with I2S_WS low. The MSB of the data is clocked out starting on the falling edge of I2S_SCK associated with the I2S_WS transition, and clocked in starting on the first rising edge of I2S_SCK following the I2S_WS transition.

Figure 10 - Left Justified Mode



Each I²S interface can support one dual channel Codec ([Figure 11](#)) through the Codec's I²S interface. The four 16-bit channel processing capacity of the DSP is spread across the two input channels from the ADCs of Codec(0) and Codec(1), and the two output channels to the DACs of Codec(0) and Codec(1).

Figure 11 - Dual Codec Configuration



Both I²S bus modes can support full bi-directional stereo communication.

The device supports I²S loopback.

See the *Microsemi AcuEdge™ Technology ZLS38052 Firmware Manual* for I²S port registers.

4.1.2 PCM Mode

Each of the PCM channels can be assigned an independent timeslot. The timeslots can be any 8-bit timeslot up to the maximum supported by the PCLK being used. The PCM ports can be configured for Narrowband G.711 A-law/ μ -Law or Linear PCM or Wideband G.722 encoding. For a given TDM bus, once it is configured for a data sample rate and encoding, all data rates and encoding on that bus will be the same. 16-bit linear PCM will be sent on consecutive 8-bit timeslots (e.g., if timeslot N is programmed in the timeslot registers, the consecutive timeslot is N+1). The PCM interface can transmit/receive 8-bit compressed or 16-bit linear data with 8 kHz sampling (Narrowband), or 16-bit linear data with 16 kHz sampling (Wideband).

Wideband audio usually means the TDM bus is operating at a 16 kHz FS, but there are two other operating modes that support wideband audio using an 8 kHz FS:

- G.722 supports wideband audio with an 8 kHz FS. This uses a single 8-bit timeslot on the TDM bus.
- “Half-FS Mode” supports wideband audio with an 8 kHz FS signal. In this mode, 16-bit linear audio is received on two timeslot pairs; the first at the specified timeslot (N, N+1) and the second a half-frame later. In total, four 8-bit timeslots are used per frame, timeslots (N, N+1) and ((N + ((bits_per_frame)/16)), (N + 1 + ((bits_per_frame)/16))). The user programs the first timeslot and the second grouping is generated automatically 125/2 μ s from the first timeslot.

The PCM voice/data bytes can occupy any of the available timeslots, except for PCM clock rates that have extra clocks in the last timeslot. If there is more than one extra clock in the last timeslot, the timeslot data will be corrupted, do not use the last timeslot for these clock frequencies (e.g., 3.088 MHz etc.).

The PCM block can be configured as a master or a slave and is compatible with the Texas Instruments Inc. McBSP mode timing format.

Figure 12 and Figure 13 illustrate the PCM format with slave timing, FS and PCLK are provided by the host. Slave mode accommodates frame sync pulses with various widths (see [“GCI and PCM Timing Parameters” on page 51](#)).

Figure 14 and Figure 15 illustrate the PCM format with master timing, FS and PCLK are provided by the ZL38052. Master mode outputs a frame sync pulse equal to one PCLK cycle.

Diagrams for PCM transmit on negative edge ($xeDX = 0$) and PCM transmit on positive edge ($xeDX = 1$) are shown for both slave and master timing.

Figure 12 - TDM – PCM Slave Functional Timing Diagram (8-bit, $xeDX = 0$)

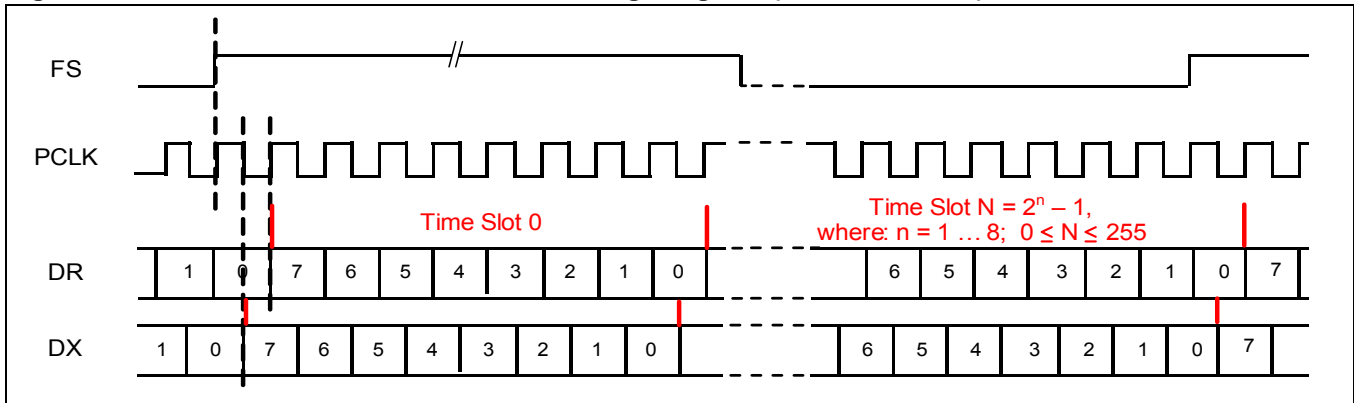


Figure 13 - TDM – PCM Slave Functional Timing Diagram (8-bit, $xeDX = 1$)

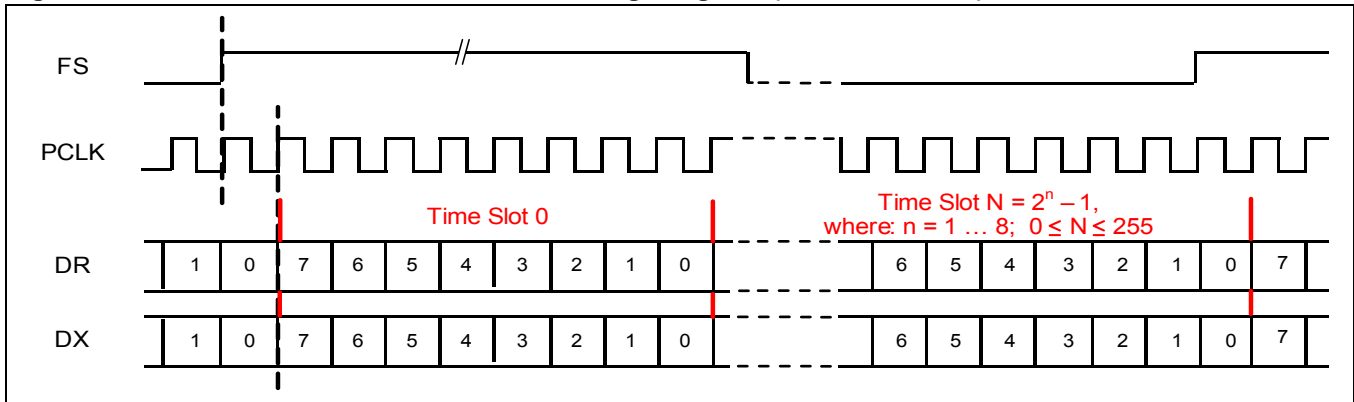


Figure 14 - TDM – PCM Master Functional Timing Diagram (8-bit, $xeDX = 0$)

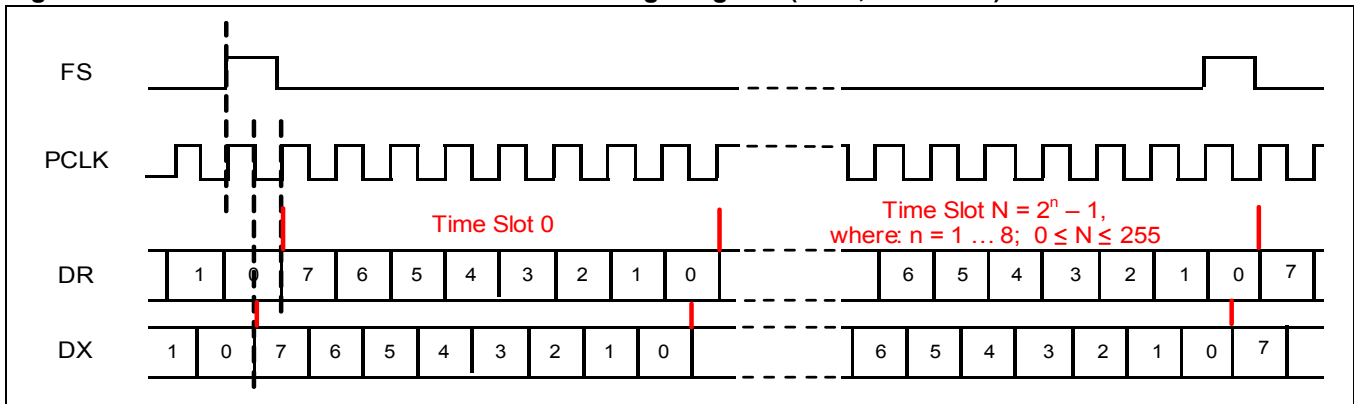
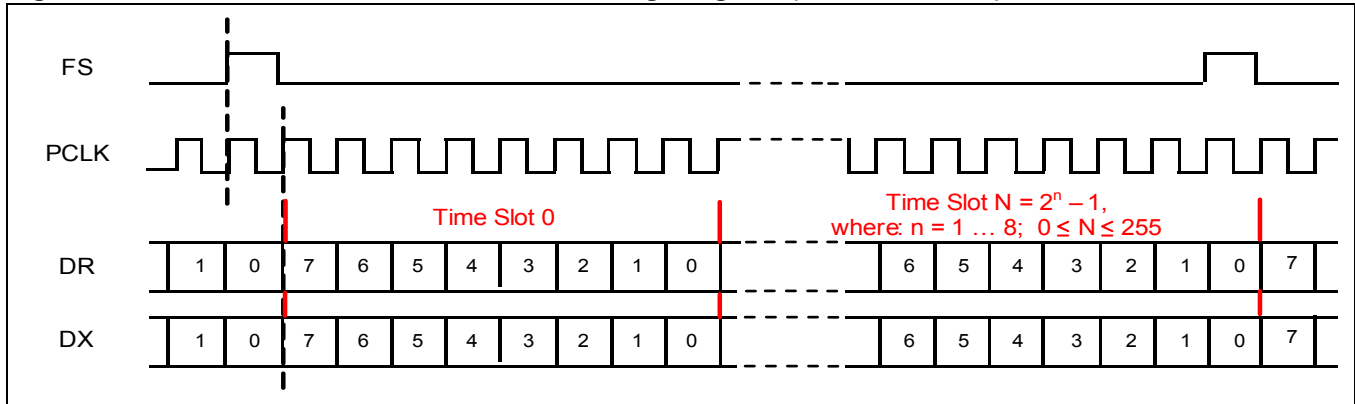


Figure 15 - TDM – PCM Master Functional Timing Diagram (8-bit, xeDX = 1)



4.1.3 GCI Mode

The GCI voice/data bytes can occupy any of the available timeslots. The GCI block can be configured as a master or a slave and supports a clock that has the same frequency as the data rate.

Note: Traditional GCI Monitor, Signalling, and Control channel bytes and double data rate are not supported.

[Figure 16](#) illustrates the GCI format with slave timing, FS and PCLK are provided by the host. Slave mode accommodates frame sync pulses with various widths (see [“GCI and PCM Timing Parameters” on page 51](#)).

[Figure 17](#) illustrates the GCI format with master timing, FS and PCLK are provided by the ZL38052. Master mode outputs a frame sync pulse equal to one PCLK cycle.

For both, first data bits are aligned with the rising edge of the frame sync pulse.

Figure 16 - TDM – GCI Slave Functional Timing Diagram

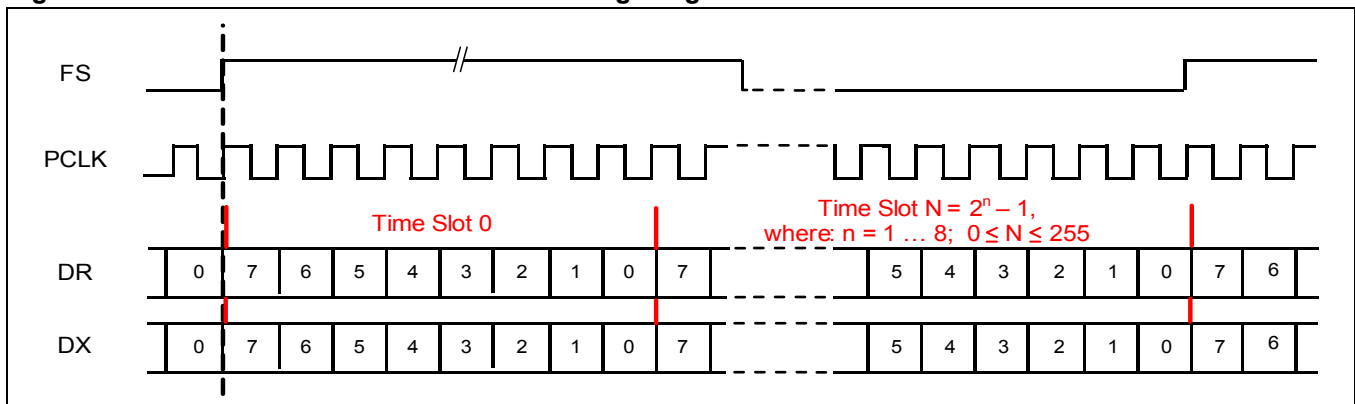
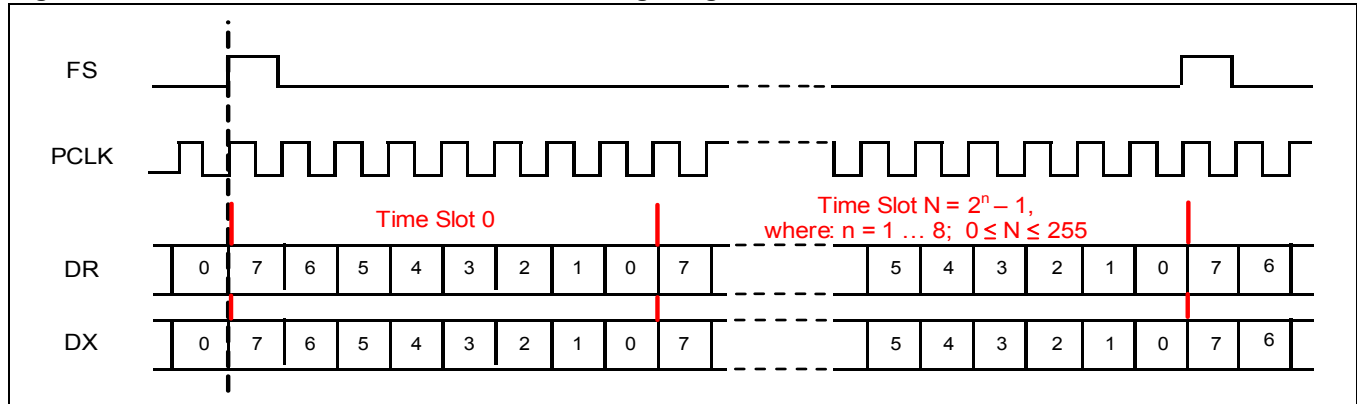


Figure 17 - TDM – GCI Master Functional Timing Diagram


4.2 Cross Point Switch

The ZL38052 contains a Cross Point Switch that allows any input port to be routed to any output port as well as routing the input/outputs to/from the audio processor functions. Refer to the *Microsemi AcuEdge™ Technology ZLS38052 Firmware Manual* for Cross Point Switch operation and control.

4.3 Host Bus Interface

The host bus interface (HBI) is the main communication port from a host processor to the ZL38052. It can be configured to be either a SPI Slave or an I²C Slave port, either of which can be used to program or query the device.

The ZL38052 allows for automatic configuration between SPI and I²C operation. For the HBI port, if the HCLK toggles for two cycles, the HBI will default to the SPI Slave, otherwise it will remain configured as I²C (see [Table 2](#)). The HBI comes up listening in both SPI and I²C modes, but with I²C inputs selected. If HCLK is present, it switches the data selection before the first byte is complete so that no bits are lost. Once the port is determined to be SPI, a hardware reset is needed to change back to I²C.

This port can read and write all of the memory and registers on the ZL38052. The port can also be used to boot the device, refer to [“Device Booting and Firmware Swapping” on page 31](#).

Table 2 - HBI Slave Interface Selection

Description	Condition	Operating Mode	Notes
HBI Slave interface selection.	HCLK toggling	Host SPI bus	1
	HDIN tied to VSS	Host I ² C bus. Slave address 45h (7-bit).	
	HDIN tied to DVDD33	Host I ² C bus. Slave address 52h (7-bit).	

Note 1: By default, the HBI comes up as an I²C interface. Toggling the HCLK pin will cause the host interface to switch to a SPI interface. If an I²C interface is desired, HCLK needs to be tied to ground.

4.3.1 SPI Slave

The physical layer is a 4-wire SPI interface. Chip select and clock are both inputs.

The SPI Slave port can support byte, word, or command framing. Write and read diagrams for these framing modes are shown in [Figure 18](#) – [Figure 23](#). The SPI Slave chip select polarity, clock polarity, and sampling phase are fixed.

The ZL38052 command protocol is half duplex, allowing the serial in and serial out to be shorted together for a 3-wire connection. The chip select is active low. The data is output on the falling edge of the clock and sampled on the rising edge of the clock.

The SPI Slave supports access rates up to 25 MHz.

The outbound interrupt is always active low.

Figure 18 - SPI Slave Byte Framing Mode – Write

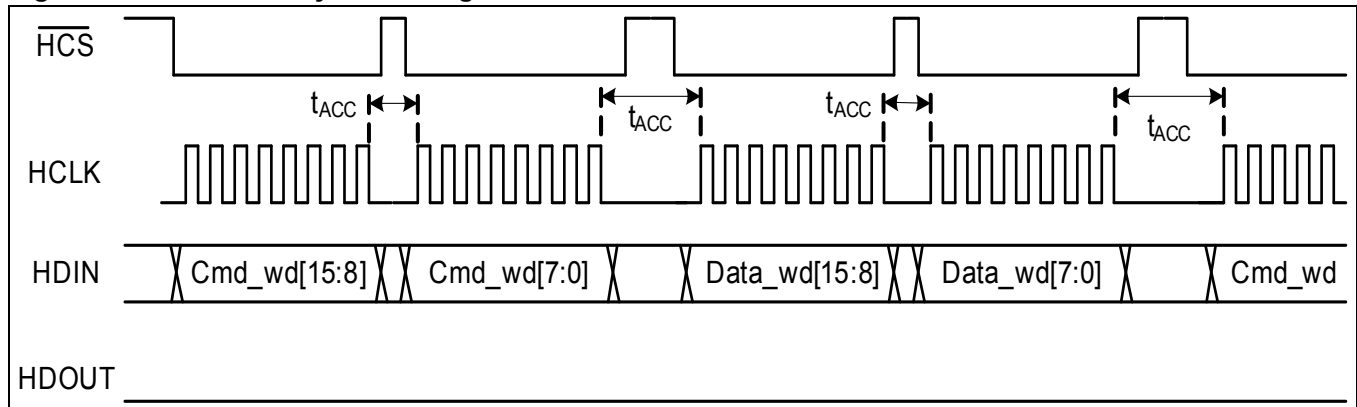


Figure 19 - SPI Slave Byte Framing Mode – Read

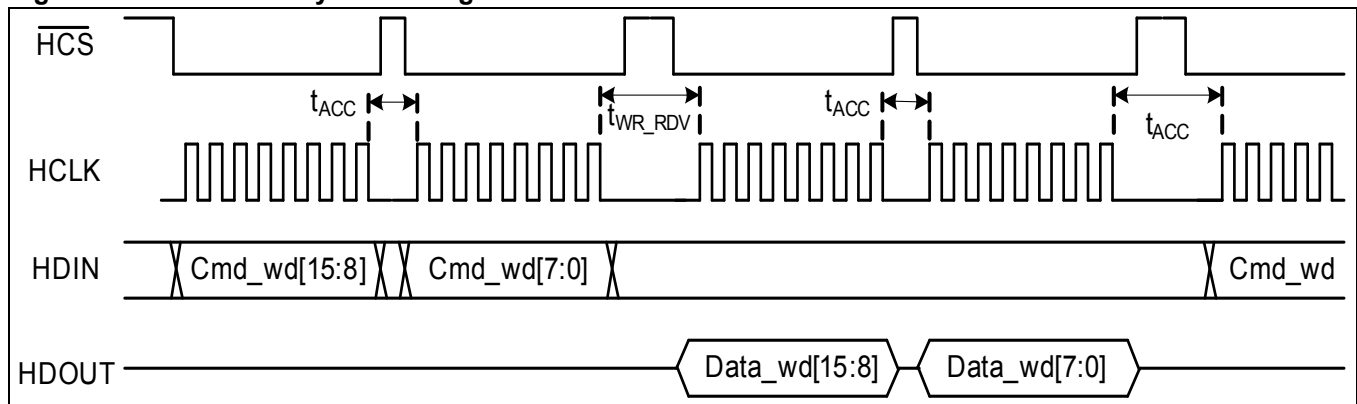


Figure 20 - SPI Slave Word Framing Mode – Write, Multiple Data Words

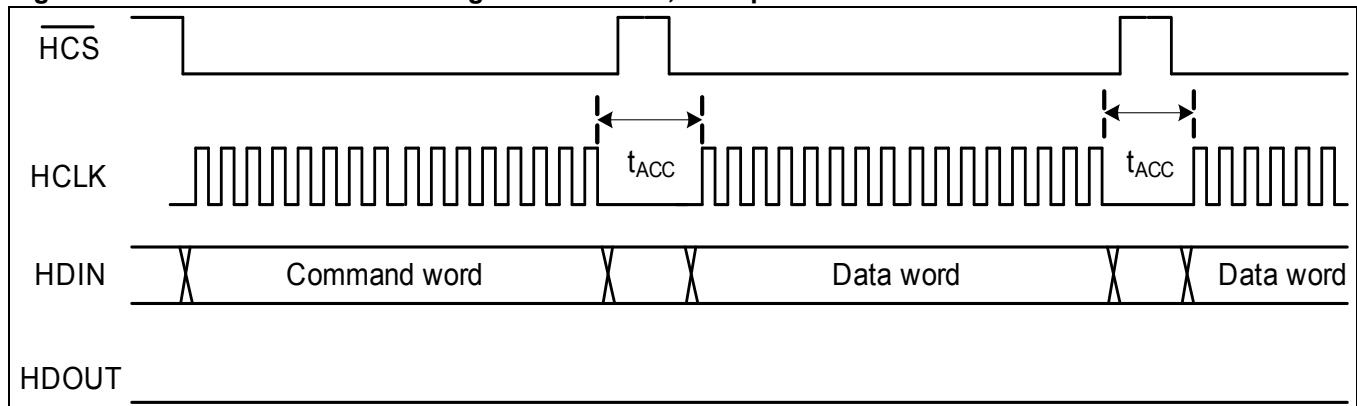


Figure 21 - SPI Slave Word Framing Mode – Read, Multiple Data Words

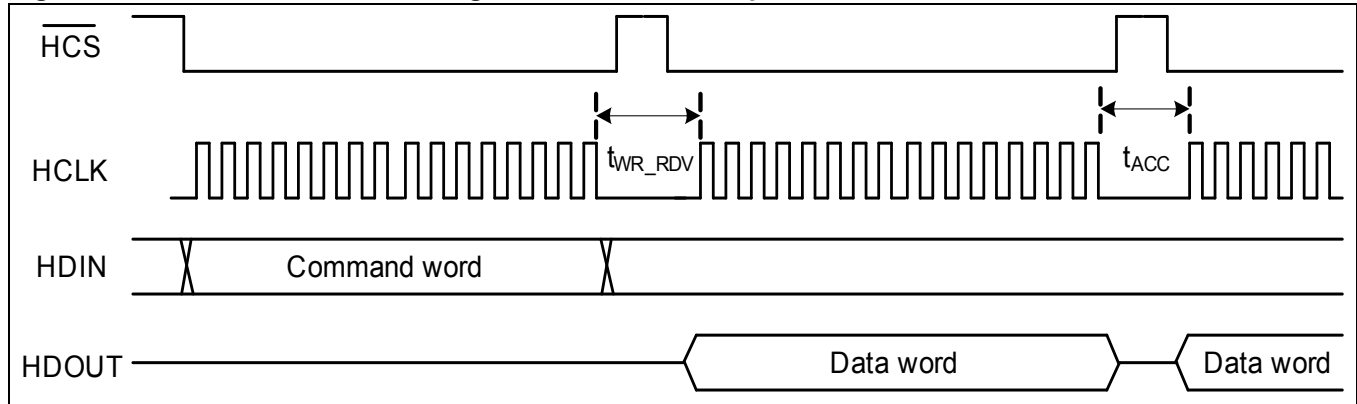


Figure 22 - SPI Slave Command Framing Mode – Write

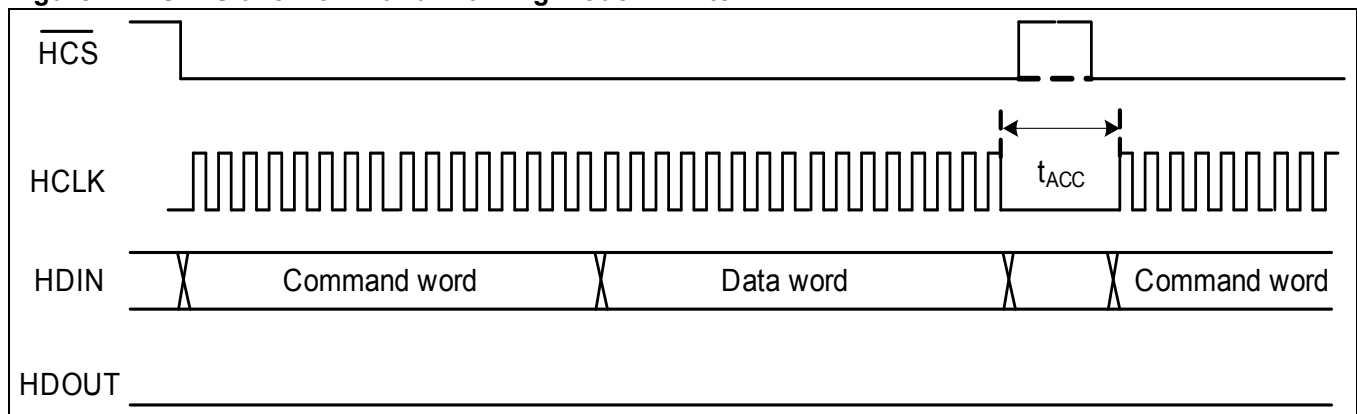
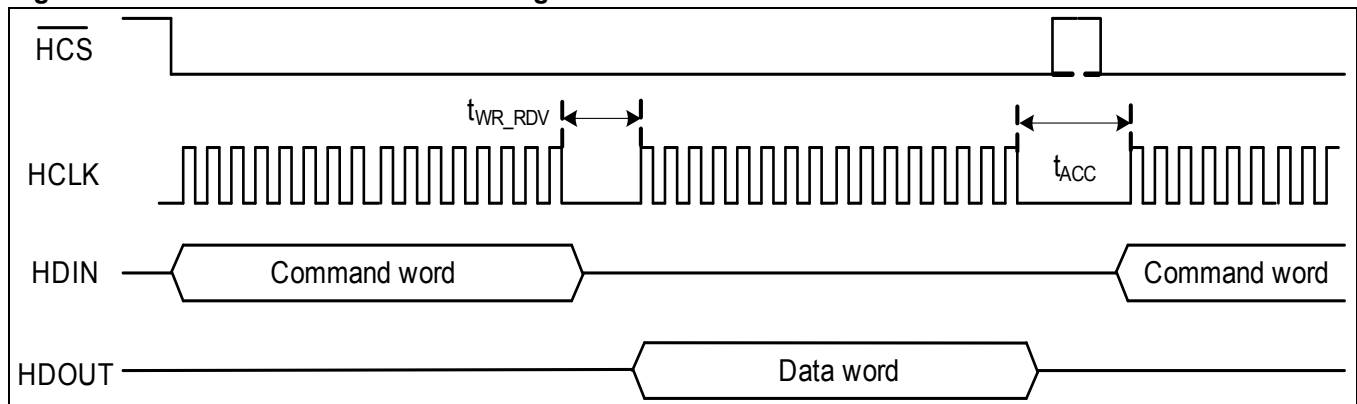


Figure 23 - SPI Slave Command Framing Mode – Read



4.3.2 I²C Slave

The I²C bus is similar to the Philips Semiconductor (NXP) 1998 Version 2.0, I²C standard. The ZL38052 I²C bus supports 7-bit addressing and transfer rates up to 400 kHz. External pull-up resistors are required on the I²C serial clock input (HCS) and the I²C serial data input/output (HDOUT) when operating in this mode (note, the I²C slave pins are 3.3 V pins and are not 5 V tolerant).

The selection of the I²C slave address is performed at bootup by the strapping of the HDIN and HCLK pins, see [Table 2](#).

4.3.3 UART

The ZL38052 device incorporates a two-wire UART (Universal Asynchronous Receiver Transmitter) interface with a fixed 115.2K baud transfer rate, 8 data bits, 1 stop and no parity. TX and RX pins allow bi-directional communication with a host. The UART pins must be made accessible on the PCB for debug and tuning purposes.

The UART port can be used as a debug tool and is used for tuning purposes.

4.3.4 Host Interrupt Pin

An internal host interrupt controller controls the active low interrupt pin which is part of the host bus interface. Associated with the interrupt controller is an event queue which reports status information for the interrupt.

Upon sensing the interrupt, the host reads the event queue to determine which event caused the interrupt. Events are enabled by the host processor, and are typically not used in a standalone (controllerless) design.

Refer to Events in the *Microsemi AcuEdge™ Technology ZLS38052 Firmware Manual* for Event ID Enumerations.

4.4 Master SPI

Like the HBI SPI Slave, the physical layer of the Master SPI is a 4-wire SPI interface supporting half duplex communication. It supports only one chip select which is multiplexed with GPIO_9.

The Master SPI is only accessible through boot ROM commands and is only used as the boot loading mechanism from an external serial Flash. The ZL38052 can automatically read the Flash data (program code and configuration record) through this interface upon the release of reset (Auto Boot), depending on the value of the bootstrap options.

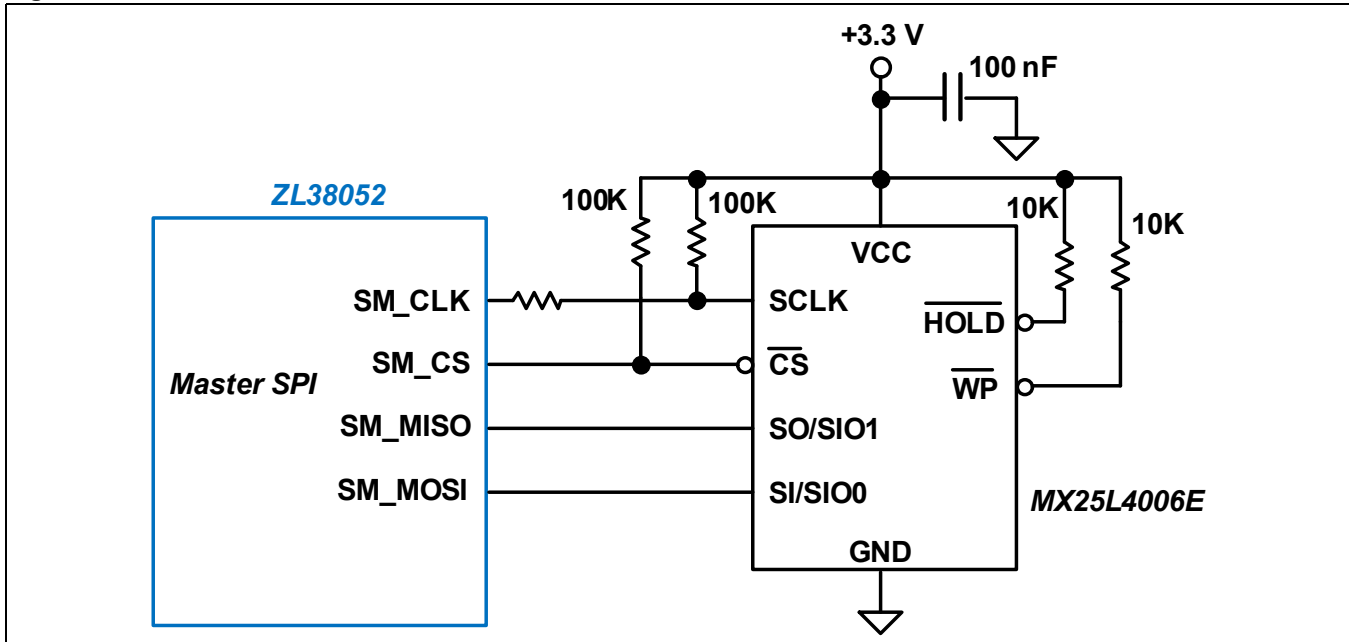
Note: An alternative to Auto Boot is to perform a Host Boot through the HBI port. Refer to [7.0, “Device Booting and Firmware Swapping” on page 31](#).

4.4.1 Flash Interface

After power-up the ZL38052 will run its resident boot code, which establishes the initial setup of the Master SPI port and then loads the firmware from external Flash memory. This Flash firmware establishes the resident application and sets the modes of all the ZL38052 ports.

[Figure 24](#) illustrates the connection of Flash memory to the ZL38052 Master SPI port. A 2 Mbit Flash is the minimum size required to store the program code and the configuration record of the ZL38052 device. The ZLE38000 demonstration hardware uses the Macronix™ MX25L4006E 4 Mbit CMOS Serial Flash device.

Figure 24 - Flash Interface Circuit



4.4.1.1 Flash Selection

The ZL38052 Boot ROM is designed to work with a wide variety of Flash devices. There are numerous Flash devices that the ZL38052 Boot ROM can recognize and program without host intervention other than a command to initialize the Flash. Other unrecognized devices may be utilized if they conform to characteristics of known devices and the host informs the ZL38052 Boot ROM of their type and size.

The ZL38052 identifies Flash devices (with a single binary image) with the ZL38052 boot ROM auto sensing the Flash type that complies with JEDEC *Manufacturer and Device ID Read Methodology for SPI Compatible Serial Interface Memory Devices*. The ZL38052 utilizes the *Serial Flash Discoverable Parameters* JEDEC standard JESD216B and the *Common Flash Interface* JESD68.01 JEDEC standard. The ZL38052 can identify devices by their JEDEC standard JEP106-K *Standard Manufacturer's Identification Code*.

A list of Flash devices that are identifiable by the ZL38052 Boot ROM are shown in [Table 3](#). The size of these devices are all 2 Mbit or 4 Mbit, the Boot ROM will also recognize the size of 8 Mbit parts that are Type 1 or Type 2 devices (as defined in [Table 4](#)).

Table 3 - Flash Devices Tested with the ZL38052

Manufacturer	Part Number	Description
Macronix™	MX25V4006EM1I-13G	4 Mbit Flash.
Winbond™	W25X40CLSNIG-ND	4 Mbit Flash.
	W25X20CLSNIG-ND	2 Mbit Flash.
Micron®	M25P20-VMN6PB	2 Mbit Flash. Large 512 Kbit sectors limit the usefulness of this device. Holds only 1 application image.
	M25P40-VMN6PB	4 Mbit Flash. Large 512 Kbit sectors limit the usefulness of this device. Holds only 2 or 3 application images.
Microchip™	SST25VF020B-80-4I	2 Mbit Flash.
Atmel®	AT25DF041A	4 Mbit Flash. Must be used in its 256 byte page variant. The default configuration is a 264 byte page. It can be ordered or programmed to use a 256 byte page.
	AT45DB041D	
Spansion™	S25FL204K0TMF1010	4 Mbit Flash.
AMIC Technology	A25L020O-F	2 Mbit Flash.

Flash devices whose JEDEC ID or size (usually a size of 16 Mbit or larger) that are not recognized by the ZL38052 Boot ROM can be made to work if they fit the characteristics of one of the 4 Flash types listed in [Table 4](#). By writing the type (1, 2, 3, or 4) to ZL38052 address 0x118 and the number of sectors to ZL38052 address 0x116 prior to initializing the Flash device, the Boot ROM will treat it as a known device of known size even though the manufacturer ID or size field are not recognized. Once the Flash is initialized, which erases and writes the Flash header, the Flash will work as a recognized Flash for all reading and programming operations.

Table 4 - Supported Flash Types

Characteristic	Type 1	Type 2	Type 3	Type 4
Sector Size	512 Kbit (64 KB)	32 Kbit (4 KB)	32 Kbit (4 KB)	16 Kbit (2 KB)
Read Status Reg Cmd	0x05	0x05	0x05	0xD7
Status Reg	Busy bit = 0x01	Busy bit = 0x01	Busy bit = 0x01	Done bit = 0x80
Data Read Cmd	0x03	0x03	0x03	0x03
Write Enable Cmd	0x06	0x06	0x06	N/A
Page Write Cmd	0x02	0x02	N/A Uses AAI to program word or byte. Uses Write Disable command to terminate AAI.	N/A Uses write from buffer command.
4-Byte Bulk Erase Cmd	N/A	N/A	N/A	0xC794809A
Examples	Micron® M25P20-VMN6PB M25P40-VMN6PB	Winbond™ W25X40CLSNIG-ND W25X20CLSNIG-ND Macronix™ MX25V4006EM1I-13G AMIC Technology A25L020O-F Spansion™ S25FL204K0TMF1010 Atmel® AT25DF041A	Microchip™ SST25VF020B-80-4I	Atmel® AT45DB021D AT45DB041D

4.5 GPIO

The ZL38052 64-pin QFN package has 14 GPIO (General Purpose Input/Output) pins; the ZL38052 56-ball WLCSP package has 11 GPIO pins.

The GPIO can be individually configured as either inputs or outputs, and have associated maskable interrupts reported to the host processor through the interrupt controller and event queue. The GPIO pins are intended for low frequency signalling.

When a GPIO pin is defined as an input, the state of that pin is sampled and latched into the GPIO Read Register. A transition on a GPIO input can cause an interrupt and event to be passed to the host processor.

Certain GPIO pins have special predefined functions, such as volume up/down, associated with that pin. Individual GPIO pins may also be defined as status outputs. See Fixed Function I/O in the *Microsemi AcuEdge™ Technology ZLS38052 Firmware Manual*.

In addition to the predefined fixed functions and the general functionality of the GPIO pins, certain GPIO pins also support bootstrap functions. Immediately after any power-on or hardware reset the GPIO pins are defined as inputs and their state is captured in the GPIO Configuration Register. The state of this register is used to determine which options are selected for the device. The GPIO pin status is then redefined as specified in the configuration record upon a load from the Flash or host. A list of bootstrap modes are found in [Table 6](#).

5.0 Reset

The device has a hardware reset pin ($\overline{\text{RESET}}$) that places the entire device into a known low power state. The device will perform either a digital or an analog reset depending on the duration of the reset pulse.

- Digital reset – When the reset pin is brought low for a duration of between 100 ns and 1 μs , a digital reset occurs and all device states and registers are reset by this pin.
- Analog reset – When the reset pin is brought low for a duration greater than 10 μs , both a digital and an analog reset will occur. The analog reset will deactivate the internally generated +1.2 V by shutting off the external FET and the internal PLL. Raising the reset pin high will immediately turn back on these supplies (requiring a corresponding PLL startup time, ~ 3 ms).

For both digital and analog reset cases when reset is released, the device will go through its boot process and the firmware will be reloaded. If the reset had been an analog reset, then the boot process will take longer waiting for the system clocks to power back on.

GPIO sensing will occur with either type of reset.

A 10 K Ω pull-up resistor is required on the $\overline{\text{RESET}}$ pin to DVDD33 if this pin is not continuously driven.

6.0 Power Supply

6.1 Power Supply Sequencing/Power up

No special power supply sequencing is required. The +3.3 V or +1.2 V power rails can be applied in either order.

Upon power-up, the ZL38052 begins to boot and senses the external resistors on the GPIO pins to determine the bootstrap settings. After 3 ms, the boot process begins and the ZL38052 takes less than 1 second to become fully operational (when auto-booting from Flash, including the time it takes to load the firmware).

In order to properly boot, the clocks to the device must be stable. This requires either the 12.000 MHz crystal or oscillator to be active, or the PCLK and frame sync of TDM-A be present and stable before the ZL38052's reset is released.

6.1.1 Power Supply Considerations

The ZL38052 requires +1.2 V to power its core DSP power supply (DVDD12). To achieve optimum noise and power performance, supply DVDD12 from an external source. Use an LDO regulator like the Microsemi LX8213 to achieve low noise and low overall power consumption. The ZL38052 is designed to minimize power in its active states when DVDD12 is supplied externally.

To further reduce power when using a crystal or clock oscillator, the internal PLL can be shut-down as described in [6.1.1.3, "Ultra-Low Power Mode"](#).

6.1.1.1 External +1.2 V Power

[Figure 25](#) shows DVDD12 powered from an external supply. A Microsemi LX8213 300 mA Low Noise CMOS LDO Regulator is shown.

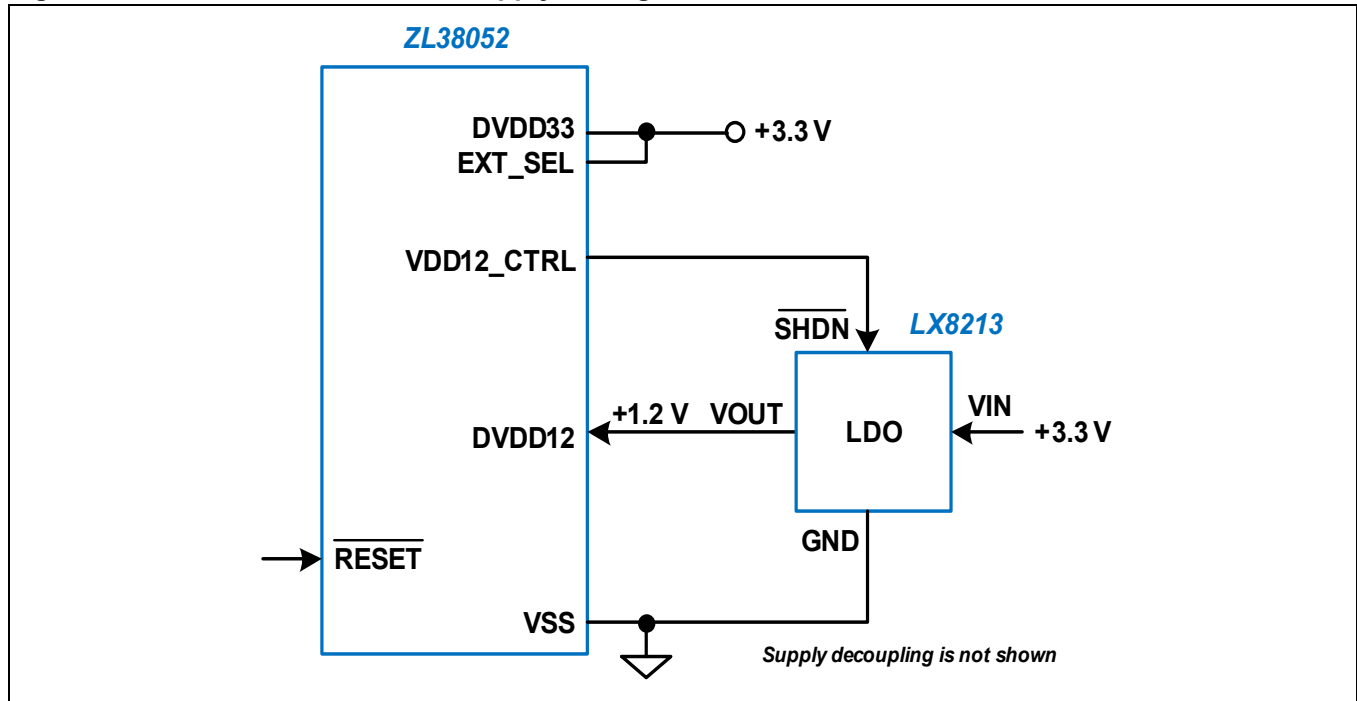
External supply is specified when the EXT_SEL pin is tied to +3.3 V. The EXT_SEL pin can be pulled high or simply hard-wired to DVDD33.

VDD12_CTRL is a CMOS output which can be used to control the shutdown of the external supply. VDD12_CTRL will provide a steady +3.3 V output (with up to 4 mA of source current) for the external supply to be enabled and 0 V for the supply to be disabled.

For power savings when the ZL38052 does not need to be operational, the external voltage regulator can be turned off by pulling the RESET pin low for longer than 10 μS (Reset mode). This action will force the VDD12_CTRL pin low, shutting off the external LDO and allowing the +1.2 V supply to collapse to 0 V.

If shutdown of the external +1.2 V supply is not desired, simply leave the VDD12_CTRL output pin floating.

Figure 25 - External +1.2 V Power Supply Configuration



6.1.1.2 Internal +1.2 V Power

Note: The internal +1.2 V power option is only available with the 64-pin QFN package. The VDD12_CTRL pin is not available on the 56-ball WLCSP package.

Alternatively, the ZL38052 has a built-in voltage regulator that can be used as the DVDD12 source. The internal voltage regulator requires an external N-channel FET device and a parallel 470 ohm resistor. [Figure 26](#) shows DVDD12 powered from the internal supply. Power dissipation is higher with internal regulator use due to the internal control circuitry and functional blocks being active.

Internal supply use is selected when the EXT_SEL pin is tied to VSS. With the built-in voltage regulator enabled, VDD12_CTRL will drive Q1 and generate +1.2 V at DVDD12. The parallel 470 ohm resistor is required to ensure supply start-up. Q1 can be any of the high power FETs shown in [Table 5](#), or an equivalent.

For power savings when the ZL38052 does not need to be operational, the internal voltage regulator can be turned off by pulling the RESET pin low for longer than 10 μS (Reset mode). This action will force the VDD12_CTRL pin low, shutting off the FET and allowing the +1.2 V supply to collapse to 0 V.

Figure 26 - Internal +1.2 V Power Supply Configuration

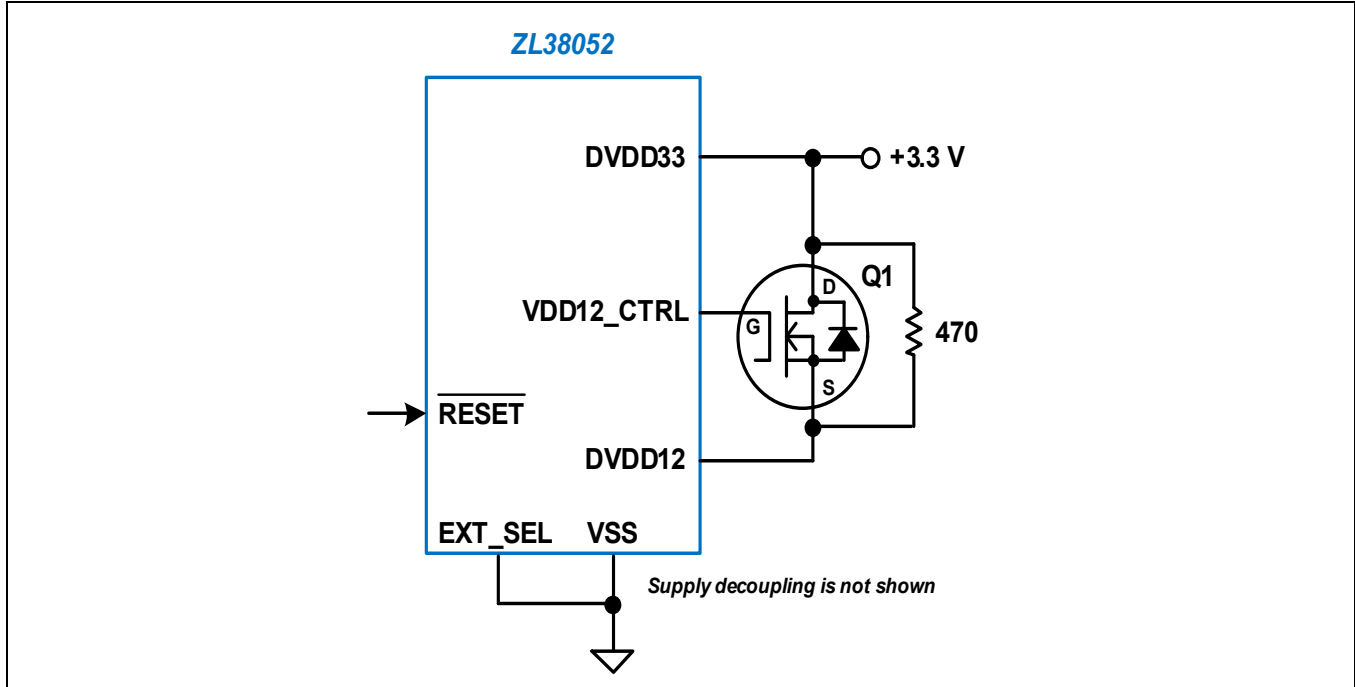


Table 5 - Q1 Component Options

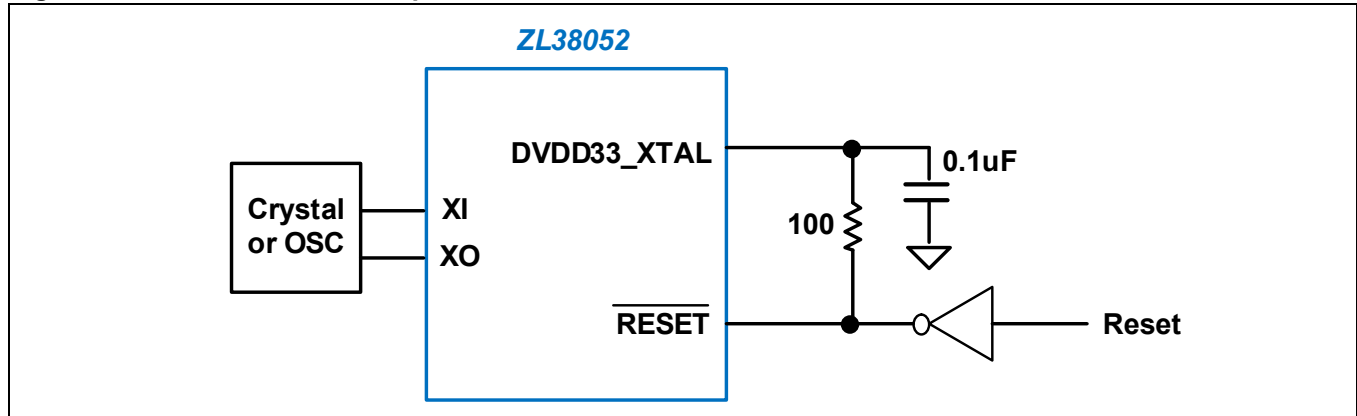
Manufacturer	Part Number
Vishay [®]	Si1422DH
International Rectifier	IRLMS2002
Diodes Inc. [®]	ZXMN2B03E6

6.1.1.3 Ultra-Low Power Mode

Note: Ultra-low power mode is only available with the 64-pin QFN package. The DVDD33_XTAL pin is not available on the 56-ball WLCSP package.

When using a crystal or clock oscillator, the ZL38052 can be placed into an Ultra-low power state by turning off the crystal oscillator’s internal voltage regulator. The circuit required to perform this is shown in [Figure 27](#).

The external circuit that drives the ZL38052 $\overline{\text{RESET}}$ pin can also be used to power the DVDD33_XTAL pin. The reset drive circuit (gate) needs to provide at least 10 mA of source current when reset is high. The series 100 ohm resistor provides a time delay to keep crystal power from reacting to short reset pulses. When the reset line goes low for longer than 10 μS , the crystal oscillator’s internal regulator will turn off and the ZL38052 will draw Ultra-low power as specified in [“Device Operating Modes” on page 43](#).

Figure 27 - Ultra-Low Power Operation Circuit


7.0 Device Booting and Firmware Swapping

7.1 Boot Loader

The ZL38052 device contains a built-in boot-loader that gets executed after a hardware reset, when power is initially applied to the part, and during the Firmware Swap process. The Bootloader performs the following actions:

- Reads the GPIO bootstrap information and stores it in the Boot Sense registers
- Depending on the bootstrap setting, it loads the external serial Flash device contents (firmware and configuration record) into Program RAM (Auto Boot), or waits for the host to load Program RAM (Host Boot and Firmware Swap)
- If Auto Boot is selected, the Bootloader then programs the ZL38052 configuration registers to their proper default values, and jumps to Program RAM to execute the firmware

7.2 Bootstrap Modes

[Table 6](#) lists the different boot options that can be selected by using external resistors. These GPIOs have internal pull-down resistors, thereby defaulting to a 0 setting. A resistor to DVDD33 is required to select a 1 option. The external pull-up resistors must have a value of 3.3 K Ω . A GPIO with a bootstrap pull-up can be used for other functionality following the power-up boot sense process.

Table 6 - Bootstrap Modes

GPIO_2	GPIO_1	GPIO_0	Operating Mode	Description	Notes
X	0	0	Crystal source 12 MHz (default)	Clock source selection	
X	0	1	TDM FSA source is 8 kHz		1
X	1	0	TDM FSA source is 16 kHz		2
X	1	1	Reserved		
0	X	X	Host Boot (default)	Boot source selection	
1	X	X	Auto Boot from external Flash		3

X = Don't care.

Note 1: Apply a 3.3 K Ω resistor from GPIO_0 to DVDD33.

Note 2: Apply a 3.3 K Ω resistor from GPIO_1 to DVDD33.

Note 3: Apply a 3.3 K Ω resistor from GPIO_2 to DVDD33. Note, when external Flash is selected, GPIO_9 = SM_CS.

7.3 Loadable Device Code

In order for the ZL38052 to operate, it must be loaded with code that resides externally. This code can either be booted from an external Flash memory through the Master SPI, or can be loaded into the ZL38052 by the host processor through the HBI port. During power-on and hardware reset, an external resistor pull-up or an internal resistor pull-down determines which boot mode will be used (see [Table 6](#)). During a Firmware Swap, the host selects which mode will be used.

The external code consists of two logical segments, the firmware code itself and the configuration record. The firmware is a binary image which contains all of the executable code allowing the ZL38052 to perform voice processing or sound detection and establishes the user command set. The configuration record contains settings for all of the user registers and defines the power-up operation of the device.

For an application that has no host and no way of externally programming the ZL38052, the configuration record is setup so that the registers are set to their desired values for normal operation. In this situation there is no way to perform a Firmware Swap. The ZL38052 will remain in either voice processing or sound detection mode.

A GUI development tool (*MiTuner™* ZLS38508) is provided to create and modify the configuration record and create a bootable Flash image which can then be duplicated for production of the end product. This tool requires access to the UART and to the I²S port for tuning (refer to [12.0, “AEC Tuning” on page 59](#)).

7.3.1 Booting and Firmware Swapping Speed

When performing an Auto Boot or Firmware Swap from a Flash device the boot sequence lasts <1 second.

When performing a Host Boot or Firmware Swap through the HBI SPI/I²C Slave port, the boot time will vary depending on the host's communications speed. The SPI port can run up to a speed of 25 MHz and has less overhead, allowing it to perform a boot download ~<300 ms; I²C is limited to a speed of 400 kHz, making a boot download last ~>5 seconds. If boot speed is important, the HBI SPI Slave port should be used for booting rather than the I²C Slave port.

7.4 Bootup Procedure

Valid clocks (PCLKA/FSA or a crystal or oscillator) must be present before the ZL38052 device can exit its reset state. After the reset line is released, the ZL38052's internal voltage regulator will be enabled (if the EXT_SEL pin is strapped low). Once the +1.2 V supply is established, the PLL will be also be enabled. Based on the GPIO bootstrap options, the ZL38052 will select the appropriate PLL source and system parameters and the PLL will lock to the desired operating frequency. An event will be placed in the event-queue and the interrupt pin (HINT) will be pulled low to signal the host when it's OK to load boot code.

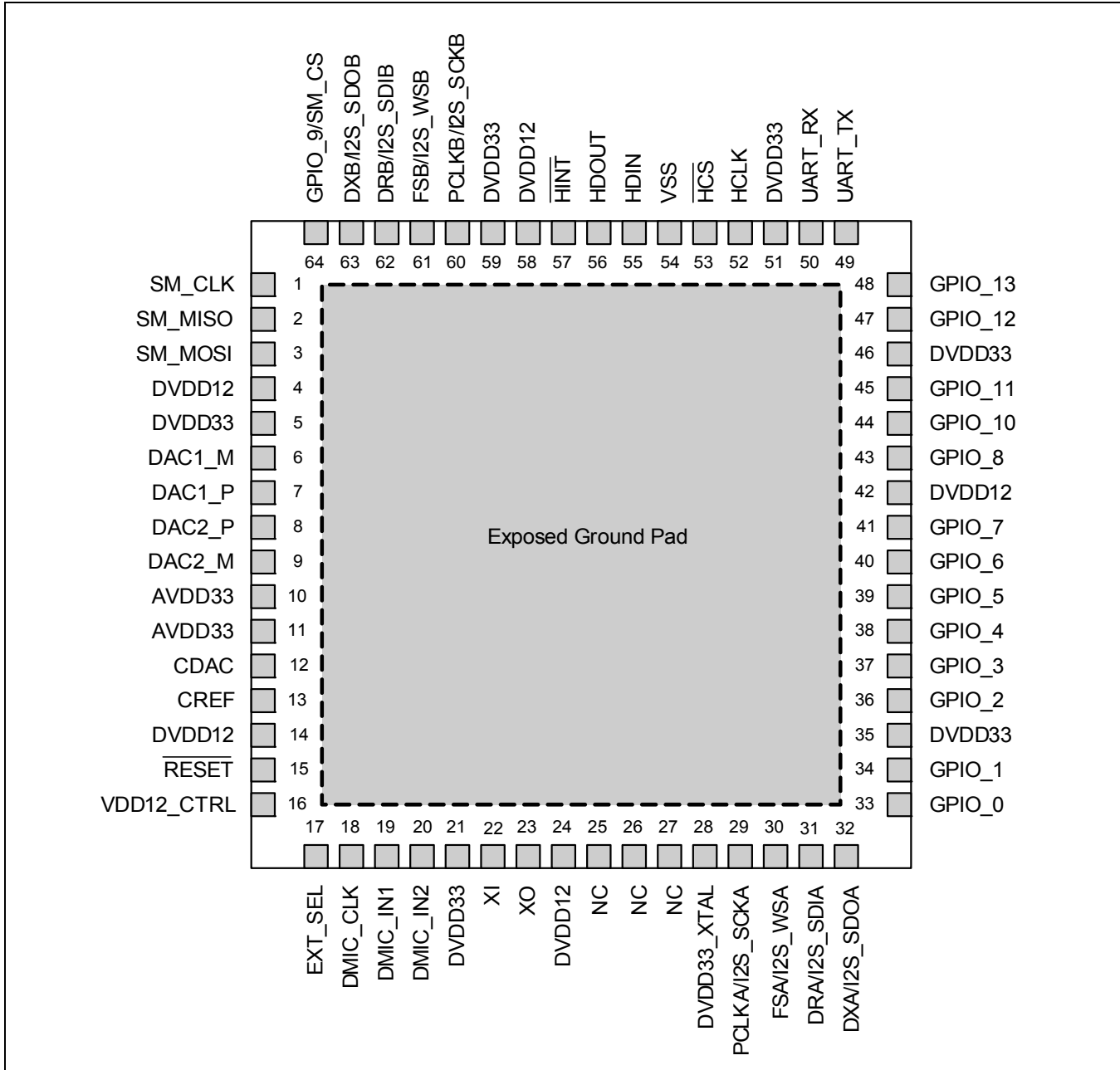
Next, if the GPIO strapping pins indicate that the ZL38052 will Auto Boot, it will begin reading data from the external Flash. Refer to the *Microsemi AcuEdge™ Technology ZLS38052 Firmware Manual* for a listing of the complete Boot Sequence.

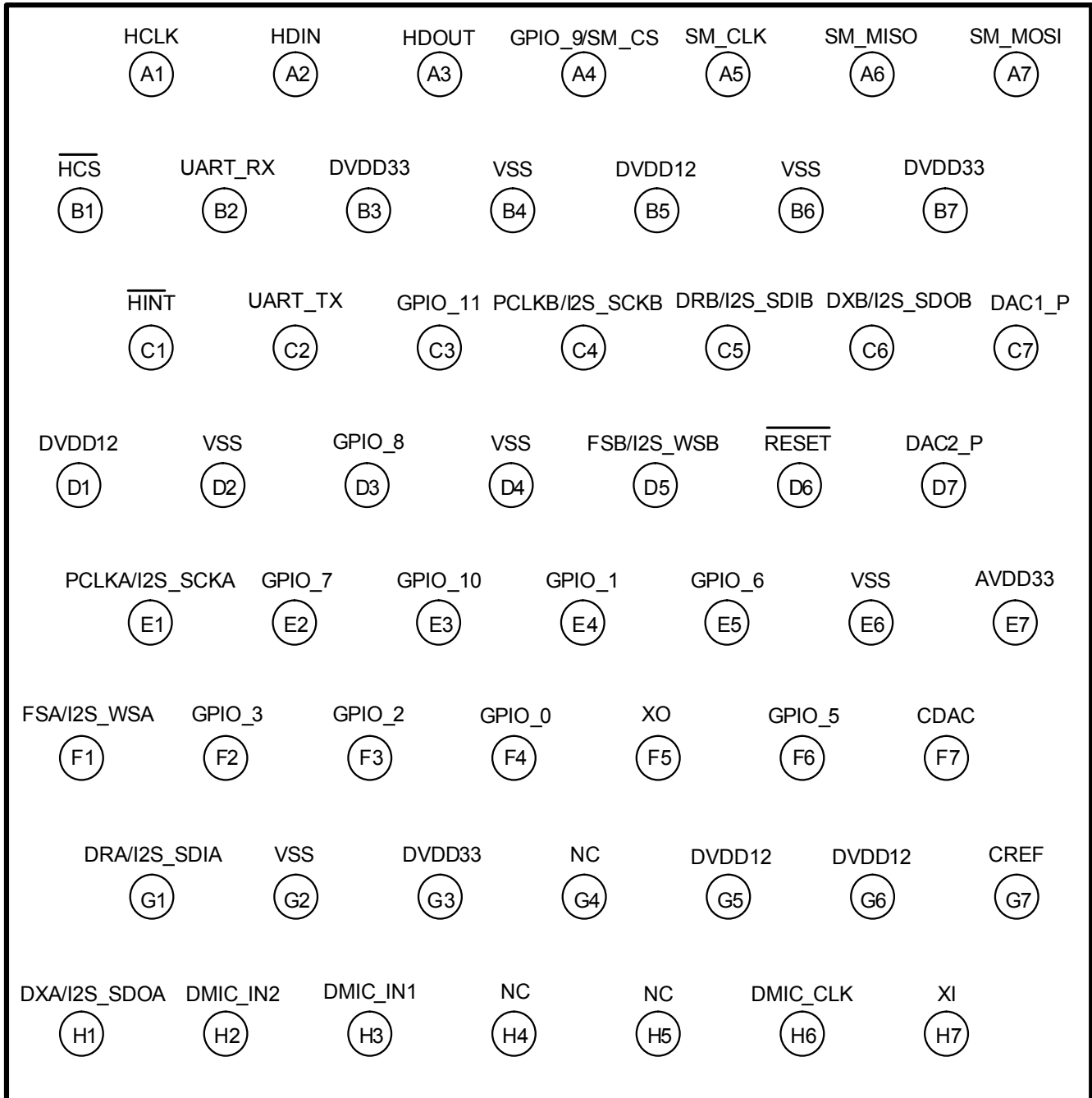
If the GPIO strapping pins indicate that the ZL38052 will Host Boot, the SPI or I²C port that initiates the loading process becomes the boot master. The ZL38052 allows for automatic configuration between SPI and I²C operation. For the HBI port, if the HCLK toggles for two cycles, the HBI will default to the SPI Slave, otherwise it will remain configured as I²C.

8.0 Device Pinouts

8.1 64-Pin QFN

Figure 28 - ZL38052 64-Pin QFN – Top View



8.2 56-Ball WLCSP
Figure 29 - ZL38052 56-Ball WLCSP – Top View


9.0 Pin Descriptions

Table 7 - Reset Pin Description

QFN Pin #	WLCSP Ball	Name	Type	Description
15	D6	$\overline{\text{RESET}}$	Input	<p>Reset. When low the device is in its reset state and all tristate outputs will be in a high impedance state. This input must be high for normal device operation. A 10 KΩ pull-up resistor is required on this node to DVDD33 if this pin is not continuously driven.</p> <p>Refer to “Reset” on page 28 for an explanation of the various reset states and their timing.</p>

Table 8 - DAC Pin Descriptions

QFN Pin #	WLCSP Ball	Name	Type	Description
6	–	DAC1_M	Output	<p>DAC 1 Minus Output. This is the negative output signal of the differential amplifier of the DAC 1. <i>Not available on the WLCSP package.</i></p>
7	C7	DAC1_P	Output	<p>DAC 1 Plus Output. This is the positive output signal of the differential amplifier of the DAC 1.</p>
9	–	DAC2_M	Output	<p>DAC 2 Minus Output. This is the negative output signal of the differential amplifier of the DAC 2. <i>Not available on the WLCSP package.</i></p>
8	D7	DAC2_P	Output	<p>DAC 2 Plus Output. This is the positive output signal of the differential amplifier of the DAC 2.</p>
12	F7	CDAC	Output	<p>DAC Reference. This pin requires capacitive decoupling. Refer to “DAC Bias Circuit” on page 13.</p>
13	G7	CREF	Output	<p>Common Mode Reference. This pin requires capacitive decoupling. Refer to “DAC Bias Circuit” on page 13.</p>

Table 9 - Microphone Pin Descriptions

QFN Pin #	WLCSP Ball	Name	Type	Description
18	H6	DMIC_CLK	Output	<p>Digital Microphone Clock Output. Clock output for digital microphones and digital electret microphone pre-amplifier devices.</p>
19	H3	DMIC_IN1	Input	<p>Digital Microphone Input 1. Stereo or mono digital microphone input. <i>Tie to VSS if unused.</i></p>
20	H2	DMIC_IN2	Input	<p>Digital Microphone Input 2. Stereo or mono digital microphone input. <i>Tie to VSS if unused.</i></p>

Table 10 - TDM and I²S Ports Pin Descriptions

The ZL38052 device has two TDM interfaces, TDM-A and TDM-B. Each TDM block is capable of being a master or

a slave. The ports can be configured for Pulse-Code Modulation (PCM) or Inter-IC Sound (I²S) operation. The ports conform to PCM, GCI, and I²S timing protocols.

QFN Pin #	WLCSP Ball	Name	Type	Description
29	E1	PCLKA/ I2S_SCKA	Input/ Output	<p>PCM Port A Clock (Input/Tristate Output). PCLKA is equal to the bit rate of signals DRA/DXA. In TDM master mode this clock is an output and in TDM slave mode this clock is an input.</p> <p>I²S Port A Serial Clock (Input/Tristate Output). This is the I²S port A bit clock. In I²S master mode this clock is an output and drives the bit clock input of the external slave device's peripheral converters. In I²S slave mode this clock is an input and is driven from a converter operating in master mode.</p> <p>After power-up, this signal defaults to be an input in I²S slave mode.</p> <p><i>A 100 KΩ pull-down resistor is required on this pin to VSS. If this pin is unused, tie the pin to VSS.</i></p> <p><i>When driving PCLKA/I2S_SCKA from a host, one of the following conditions must be satisfied:</i></p> <ol style="list-style-type: none"> <i>Host drives PCLKA low during reset, or</i> <i>Host tri-states PCLKA during reset (the 100 KΩ resistor will keep PCLKA low), or</i> <i>Host drives PCLKA at its normal frequency</i>
30	F1	FSA/ I2S_WSA	Input/ Output	<p>CM Port A Frame Sync (Input/Tristate Output). This is the TDM frame alignment reference. This signal is an input for applications where the PCM bus is frame aligned to an external frame signal (slave mode). In master mode this signal is a frame pulse output.</p> <p>I²S Port A Word Select (Left/Right) (Input/Tristate Output). This is the I²S port A left or right word select. In I²S master mode word select is an output which drives the left/right input of the external slave device's peripheral converters. In I²S slave mode this pin is an input which is driven from a converter operating in master mode.</p> <p>After power-up, this signal defaults to be an input in I²S slave mode. <i>Tie this pin to VSS if unused.</i></p>
31	G1	DRA/ I2S_SDIA	Input	<p>PCM Port A Serial Data Stream Input. This serial data stream operates at PCLK data rates.</p> <p>I²S Port A Serial Data Input. This is the I²S port serial data input.</p> <p><i>Tie this pin to VSS if unused.</i></p>
32	H1	DXA/ I2S_SDOA	Output	<p>PCM Port A Serial Data Stream Output. This serial data stream operates at PCLK data rates.</p> <p>I²S Port A Serial Data Output. This is the I²S port serial data output.</p>

QFN Pin #	WLCSP Ball	Name	Type	Description
60	C4	PCLKB/ I2S_SCKB	Input/ Output	<p>PCM Port B Clock (Input/Tristate Output). PCLKB is equal to the bit rate of signals DRB/DXB. In TDM master mode this clock is an output and in TDM slave mode this clock is an input.</p> <p>I²S Port B Serial Clock (Input/Tristate Output). This is the I²S port B bit clock. In I²S master mode this clock is an output and drives the bit clock input of the external slave device's peripheral converters. In I²S slave mode this clock is an input and is driven from a converter operating in master mode.</p> <p>After power-up, this signal is an input in I²S slave mode. <i>Tie this pin to VSS if unused.</i></p>
61	D5	FSB/ I2S_WSB	Input/ Output	<p>PCM Port B Frame Sync (Input/Tristate Output). This is the TDM frame alignment reference. This signal is an input for applications where the PCM bus is frame aligned to an external frame signal (slave mode). In master mode this signal is a frame pulse output.</p> <p>I²S Port B Word Select (Left/Right) (Input/Tristate Output). This is the I²S port B left or right word select. In I²S master mode word select is an output which drives the left/right input of the external slave device's peripheral converters. In I²S slave mode this pin is an input which is driven from a converter operating in master mode.</p> <p>After power-up, this signal defaults to be an input in I²S slave mode. <i>Tie this pin to VSS if unused.</i></p>
62	C5	DRB/ I2S_SDIB	Input	<p>PCM Port B Serial Data Stream Input. This serial data stream operates at PCLK data rates.</p> <p>I²S Port B Serial Data Input. This is the I²S port serial data input.</p> <p><i>Tie this pin to VSS if unused.</i></p>
63	C6	DXB/ I2S_SDOB	Output	<p>PCM Port B Serial Data Stream Output. This serial data stream operates at PCLK data rates.</p> <p>I²S Port B Serial Data Output. This is the I²S port serial data output.</p>

Table 11 - HBI – SPI Slave Port Pin Descriptions

This port functions as a peripheral interface for an external controller, and supports access to the internal registers and memory of the device.

QFN Pin #	WLCSP Ball	Name	Type	Description
52	A1	HCLK	Input	HBI SPI Slave Port Clock Input. Clock input for the SPI Slave port. Maximum frequency = 25 MHz. This input should be tied to VSS in I ² C mode, refer to Table 2 . <i>Tie this pin to VSS if unused.</i>
53	B1	$\overline{\text{HCS}}$	Input	HBI SPI Slave Chip Select Input. This active low chip select signal activates the SPI Slave port. HBI I²C Serial Clock Input. This pin functions as the I2C_SCLK input in I ² C mode. A pull-up resistor is required on this node for I ² C operation. <i>Tie this pin to VSS if unused.</i>
55	A2	HDIN	Input	HBI SPI Slave Port Data Input. Data input signal for the SPI Slave port. This input selects the slave address in I ² C mode, refer to Table 2 . <i>Tie this pin to VSS if unused.</i>
56	A3	HDOUT	Input/Output	HBI SPI Slave Port Data Output (Tristate Output). Data output signal for the SPI Slave port. HBI I²C Serial Data (Input/Output). This pin functions as the I2C_SDA I/O in I ² C mode. A pull-up resistor is required on this node for I ² C operation.
57	C1	$\overline{\text{HINT}}$	Output	HBI Interrupt Output. This output can be configured as either CMOS or open drain by the host.

Table 12 - Master SPI Port Pin Descriptions

This port functions as the interface to an external Flash device used to optionally Auto Boot and load the device's firmware and configuration record from external Flash memory.

QFN Pin #	WLCSP Ball	Name	Type	Description
1	A5	SM_CLK	Output	Master SPI Port Clock (Tristate Output). Clock output for the Master SPI port. Maximum frequency = 8 MHz.
2	A6	SM_MISO	Input	Master SPI Port Data Input. Data input signal for the Master SPI port.
3	A7	SM_MOSI	Output	Master SPI Port Data Output (Tristate Output). Data output signal for the Master SPI port.

QFN Pin #	WLCSP Ball	Name	Type	Description
64	A4	GPIO_9/ SM_CS	Input/ Output	Master SPI Port Chip Select (Input Internal Pull-Up/Tristate Output). Chip select output for the Master SPI port. Shared with GPIO_9, see Table 14 .

Table 13 - UART Pin Descriptions

The ZL38052 device incorporates a two-wire UART (Universal Asynchronous Receiver Transmitter) interface with a fixed 115.2K baud transfer rate, 8 data bits, 1 stop and no parity. The UART port can be used as a debug tool and is used for tuning purposes.

QFN Pin #	WLCSP Ball	Name	Type	Description
50	B2	UART_RX	Input	UART (Input). Receive serial data in. This port functions as a peripheral interface for an external controller and supports access to the internal registers and memory of the device.
49	C2	UART_TX	Output	UART (Tristate Output). Transmit serial data out. This port functions as a peripheral interface for an external controller and supports access to the internal registers and memory of the device.

Table 14 - GPIO Pin Descriptions

GPIO ports can be used for interrupt and event reporting, fixed function control, bootstrap options, as well as being used for general purpose I/O for communication and controlling external devices.

QFN Pin #	WLCSP Ball	Name	Type	Description
33, 34, 36	F4, E4, F3	GPIO_[0:2]	Input/ Output	General Purpose I/O (Input Internal Pull-Down/Tristate Output). These pins can be configured as an input or output and are intended for low-frequency signalling. Refer to Table 6 for bootstrap functionality.
37, 38, 39, 40, 41, 43	F2, –, F6, E5, E2, D3	GPIO_[3:8]	Input/ Output	General Purpose I/O (Input Internal Pull-Down/Tristate Output). These pins can be configured as an input or output and are intended for low-frequency signalling. <i>GPIO_4 is not available on the WLCSP package.</i>
64	A4	GPIO_9/ SM_CS	Input/ Output	General Purpose I/O (Input Internal Pull-Down/Tristate Output). This pin can be configured as an input or output and is intended for low-frequency signalling. Alternate functionality with SM_CS, see Table 12 .
44, 45, 47, 48	E3, C3, –, –	GPIO_ [10:13]	Input/ Output	General Purpose I/O (Input Internal Pull-Down/Tristate Output). These pins can be configured as an input or output and are intended for low-frequency signalling. <i>GPIO_12 and GPIO_13 are not available on the WLCSP package.</i>

Table 15 - Oscillator Pin Descriptions

These pins are connected to a 12.000 MHz crystal or clock oscillator which drives the device's internal PLL. Alternatively, PCLKA can be used as the internal clock source.

QFN Pin #	WLCSP Ball	Name	Type	Description
22	H7	XI	Input	Crystal Oscillator Input. Refer to “External Clock Requirements” on page 48.
23	F5	XO	Output	Crystal Oscillator Output. Refer to “External Clock Requirements” on page 48.

Table 16 - Supply and Ground Pin Descriptions

QFN Pin #	WLCSP Ball	Name	Type	Description
17	–	EXT_SEL	Input	VDD +1.2 V Select. Select external +1.2 V supply. Tie to DVDD33 if the +1.2 V supply is to be provided externally. Tie to VSS (0 V) if the +1.2 V supply is to be generated internally. Refer to 6.1.1, “Power Supply Considerations” for more information. <i>Not available on the WLCSP package.</i>
16	–	VDD12_CTRL	Output	VDD +1.2 V Control. Analog control line for the voltage regulator external FET when EXT_SEL is tied to VSS. When EXT_SEL is tied to DVDD33, the VDD12_CTRL pin becomes a CMOS output which can drive the shutdown input of an external LDO. Refer to 6.1.1, “Power Supply Considerations” for more information. <i>Not available on the WLCSP package.</i>
4, 14, 24, 42, 58	B5, D1, G5, G6	DVDD12	Power	Core Supply. Connect to a +1.2 V ±5% supply. <i>Place a 100 nF, 20%, 10 V, ceramic capacitor on each pin decoupled to the VSS plane.</i> Refer to 6.1.1, “Power Supply Considerations” for more information.
5, 21, 35, 46, 51, 59	B3, B7, G3	DVDD33	Power	Digital Supply. Connect to a +3.3 V ±5% supply. <i>Place a 100 nF, 20%, 10 V, ceramic capacitor on each pin decoupled to the VSS plane.</i>
28	–	DVDD33_XTAL	Power	Crystal Digital Supply. For designs using a crystal or external oscillator, this pin must be connected to a +3.3 V supply source capable of delivering 10 mA. For designs that do not use a crystal or external oscillator this pin can be tied to VSS in order to save power. <i>Not available on the WLCSP package.</i>
10, 11	E7	AVDD33	Power	Analog Supply. Connect to a +3.3 V ±5% supply. <i>Place a 100 nF, 20%, 10 V, ceramic capacitor on each pin decoupled to the VSS plane.</i>
54	B4, B6, D2, D4, E6, G2	VSS	Ground	Ground. Connect to digital ground plane.
	–	Exposed Ground Pad	Ground	Exposed Pad Substrate Connection. Connect to VSS. This pad is at ground potential and must be soldered to the printed circuit board and connected via multiple vias to a heatsink area on the bottom of the board and to the internal ground plane. <i>Not available on the WLCSP package.</i>

Table 17 - No Connect Pin Description

QFN Pin #	WLCSP Ball	Name	Type	Description
25, 26, 27	G4, H4, H5	NC		No Connection. These pins are to be left unconnected, do not use as a tie point.

10.0 Electrical Characteristics

10.1 Absolute Maximum Ratings

Stresses above those listed under *Absolute Maximum Ratings* can cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

Supply voltage (DVDD33, AVDD33)	-0.5 to +4.0 V
Core supply voltage (DVDD12)	-0.5 to +1.32 V
Input voltage	-0.5 to +4.0 V
Continuous current at digital outputs	15 mA
Reflow temperature, 10 sec., MSL3, per <i>JEDEC J-STD-020</i>	260 °C
Storage temperature	-55 to +125 °C
ESD immunity (Human Body Model)	JESD22 Class 1C compliant

10.2 Thermal Resistance

Junction to ambient thermal resistance ⁽¹⁾ , θ_{JA}	64-pin QFN	22.1 °C/W
	56-ball WLCSP	33.8 °C/W
Junction to board thermal resistance ⁽¹⁾ , θ_{JB}	64-pin QFN	6.1 °C/W
	56-ball WLCSP	3.9 °C/W
Junction to exposed pad thermal resistance ⁽¹⁾ , θ_{JC}	64-pin QFN	2.0 °C/W
Junction to case thermal resistance ⁽¹⁾ , θ_{JC}	56-ball WLCSP	5.2 °C/W
Junction to top characterization parameter, ψ_{JT}	64-pin QFN	0.1 °C/W
	56-ball WLCSP	0.3 °C/W

Notes:

- The thermal specifications assume that the device is mounted on an effective thermal conductivity test board (4 layers, 2s2p) per *JEDEC JESD51-7* and *JESD51-5*.

10.3 Operating Ranges

Microsemi guarantees the performance of this device over the industrial (-40 °C to 85 °C) temperature range by conducting electrical characterization over each range and by conducting a production test with single insertion coupled to periodic sampling. These characterization and test procedures comply with the *Telcordia GR-357-CORE Generic Requirements for Assuring the Reliability of Components Used in Telecommunications Equipment*.

Parameter	Symbol	Min.	Typ.	Max.	Units
Ambient temperature	T_A	-40		+85	°C
Analog supply voltage	V_{AVDD33}	3.135	3.3	3.465	V
Digital supply voltage	V_{DVDD33}				
Crystal Digital supply voltage	V_{DVDD33_XTAL}				
Crystal I/O voltage	V_{XI}		2.5	2.625	V
Core supply voltage	V_{DVDD12}	1.14	1.2	1.26	V

10.4 Device Operating Modes

The ZL38052 has six standard modes of operation. Normal operation is when the ZL38052 is running during Full Duplex Communication Mode. Sound Classifier mode is detailed in the ZLS38052 Firmware Guide. Low-Power and Sleep modes are programmable options to reduce power consumption. Reset and Ultra-Low Power modes are hardware modes that can be utilized to further minimize power consumption. These are all highlighted in the following sections.

Refer to the *Microsemi AcuEdge™ Technology ZLS38052 Firmware Manual* for programming and additional information on the firmware operating modes.

10.4.1 Normal (ZLS38052.0)

- Normal firmware mode
- HBI active
- Audio path active
- DACs and MICs can be enabled
- Audio Processor always on

Normal mode is recommended for applications that use the internal voltage regulator with analog microphones. Normal mode keeps the Audio Processor always on, thereby minimizing +1.2 V power supply noise that could be injected into sensitive analog microphone circuitry via the board layout.

10.4.2 Low-Power (ZLS38052.0)

- Low-Power firmware mode
- HBI active
- Audio path active
- DACs and MICs can be enabled
- Audio Processor operates in Power Saving Mode

Low-power mode is selected in register 0x206 (System Control Flags) bit 1, or can be selected from the ZLS38508 *MiTuner™* GUI in the AEC Control window (Enable Power Saving Mode). Low-Power mode is not recommended for applications that use the internal voltage regulator with analog microphones.

10.4.3 Sound Classifier (ZLS38052.2)

- Glass breaking detection
- Programmable Energy Detector
- Temporal pattern detection
- HBI active
- One MIC active
- DACs disabled
- Audio Processor operates in Power Saving Mode

10.4.4 Sleep (ZLS38052.0)

- Sleep firmware mode
- HBI active
- Audio path inactive

- DACs and MICs are powered down
- Audio Processor made inactive, internal clocks are shutdown, requires a wake-up procedure to return to Normal or Low-Power mode

The ZL38052 will respond to no other inputs until it awakens from Sleep mode. To wake from Sleep mode, perform an HBI Wake From Sleep operation, as described in the *ZLS38052 Firmware Manual* Appendix D. The firmware and configuration records loaded into the device RAM are retained, no re-boot is required.

10.4.5 Reset

- Hardware mode, the ZL38052 goes into this mode when the $\overline{\text{RESET}}$ pin is held low for greater than 10 μS
- HBI inactive
- Audio path inactive
- DACs and MICs are powered down
- Audio Processor powered down via removal of +1.2 V supply

See [5.0, "Reset" on page 28](#) for more information and refer to [6.0, "Power Supply" on page 28](#) for information on +1.2 V removal.

10.4.6 Ultra-Low Power

- Hardware mode when using an external crystal or crystal oscillator, the hardware can be configured to enter this mode when the $\overline{\text{RESET}}$ pin is held low for greater than 10 μS
- HBI inactive
- Audio path inactive
- DACs and MICs are powered down
- Audio Processor powered down via removal of +1.2 V supply
- Crystal or crystal oscillator supply made inactive

See [5.0, "Reset" on page 28](#) and [6.1.1.3, "Ultra-Low Power Mode" on page 30](#) for more information, refer to [6.0, "Power Supply" on page 28](#) for information on +1.2 V removal.

10.4.7 Current Consumption

Device current consumption can vary with the firmware load. Common values are listed here using an external +1.2 V supply for the core power supply with PCLKA as the external clock source for the PLL and a 3.3 K Ω resistor from GPIO_2 to DVDD33 (external Flash selected), unless otherwise noted.

Operational Mode	+3.3 V ¹		+1.2 V ²		Units	Notes / Conditions
	Typ.	Max.	Typ.	Max.		
Normal (ZLS38052.0)	9.8		125		mA	Firmware active, power-saving off, 1 DAC active ³ , 2 MICs active ⁴ .
Low-Power (ZLS38052.0)	9.8		87.5			Firmware active, power-saving on, 1 DAC active ³ , 2 MICs active ⁴ .
Sleep (ZLS38052.0)	2.5		3.8			Firmware inactive (Firmware and configuration record are retained), DACs and MICs are powered down, HBI is active.
Sound Classifier (ZLS38052.2)	4.5		47.5			Sound Classification Firmware active, 1 MIC active, DACs disabled, HBI is active, **measured in quiet environment
Reset	100		0		μ A	Device in reset (reset > 10 μ S), DVDD12 removed ⁵ .
Ultra-Low Power	3		0			Crystal or crystal oscillator in use. Device in reset (reset > 10 μ S), DVDD12 not present, DVDD33_XTAL held low.

Note 1: Table values include all current entering DVDD33, AVDD33, and DVDD33_XTAL pins.
 Add 1.0 mA to Normal, Low-Power, and Sleep modes if the internal voltage regulator is used (EXT_SEL = VSS).
 Add 1.1 mA to Normal, Low-Power, and Sleep modes if a crystal or crystal oscillator is used (DVDD33_XTAL = +3.3 V).

Note 2: Core supply voltage. Table values include all current entering DVDD12 pins.

Note 3: For 2 DACs active, add 3.6 mA to +3.3 V current.

Note 4: If 3 MICs are active, add 0.6 mA to +1.2 V current.

Note 5: DVDD12 is removed if the internal regulator is used for +1.2 V generation or if the VDD12_CTRL pin is used to shutdown an external +1.2 V LDO that provides DVDD12 to the ZL38052.

10.5 DC Specifications

Typical values are for TA = 25 °C and nominal supply voltage. Minimum and maximum values are over the industrial -40 °C to 85 °C temperature range and supply voltage range as shown in [“Operating Ranges” on page 42](#), except as noted. A 12 MHz crystal oscillator is active.

Parameter	Symbol	Min.	Typ.	Max.	Units	Notes / Conditions
Input high voltage	V _{IH}	0.7 * V _{DVDD33}		V _{DVDD33} + 0.3	V	All digital inputs
Input low voltage	V _{IL}	V _{VSS} - 0.3		0.3 * V _{DVDD33}	V	All digital inputs
Input hysteresis voltage	V _{HYS}	0.4			V	
Input leakage (input pins)	I _{IL}			5	μA	0 to +3.3 V
Input leakage (bi-directional pins)	I _{BL}			5	μA	0 to +3.3 V
Weak pull-up current	I _{PU}	38	63	101	μA	Input at 0 V
Weak pull-down current	I _{PD}	19	41	158	μA	Input at +3.3 V
Input pin capacitance	C _I		5		pF	
Output high voltage	V _{OH}	2.4			V	At 12 mA
Output low voltage	V _{OL}			0.4	V	At 12 mA
Output high impedance leakage	I _{OZ}			5	μA	0 to +3.3 V
Pin capacitance (output & input/tristate pins)	C _O		5		pF	
Output rise time	t _{RT}		1.25		ns	10% to 90%, C _{LOAD} = 20 pF
Output fall time	t _{FT}		1.25		ns	90% to 10%, C _{LOAD} = 20 pF

10.6 AC Specifications

For all AC specifications, typical values are for TA = 25 °C and nominal supply voltage. Minimum and maximum values are over the industrial -40 °C to 85 °C temperature range and supply voltage ranges as shown in [“Operating Ranges” on page 42](#), except as noted. A 12.000 MHz crystal oscillator is active, ZL38052 in Normal, Wideband operational mode.

10.6.1 Microphone Interface

Parameter	Symbol	Min.	Typ.	Max.	Units	Notes / Conditions
Microphone clock output (DMIC_CLK), 8 kHz, 16 kHz sample rate 48 kHz sample rate			1.024 3.072		MHz MHz	
DMIC_CLK, Output high current	I _{OH}		20		mA	V _{OH} = DVDD33 - 0.4 V
DMIC_CLK, Output low current	I _{OL}		30		mA	V _{OL} = 0.4 V
DMIC_CLK, Output rise and fall time	t _R , t _F		5		ns	C _{LOAD} = 100 pF

10.6.2 DAC

Measurements taken using PCM mode. THD+N versus output power for speaker drive applications presented in [Figure 30](#); THD+N versus output voltage for amplifier drive applications presented in [Figure 31](#).

Parameter	Symbol	Min.	Typ.	Max.	Units	Notes / Conditions
DAC output level: Full scale: Differential Single-ended 0 dBm0 : Differential Single-ended	V_{DACFS}		4.8 2.4 2.8 1.4		V_{PP}	DAC gain = 1, 1 K Ω load.
PCM full scale level (V_{ppd} value)			9		dBm0	DAC gain = 1, 600 Ω load
DAC output power: Single-ended, 32 ohm load Single-ended, 16 ohm load Differential, 32 ohm load			20.6 37.5 86.0	24 47 94	mW	1, Single-ended loads driven capacitively to ground
Frequency response: Sample rate = 48 kS/s	f_R	20		20000	Hz	1, 3 dB cutoff includes external AC coupling, without AC coupling the response is low pass.
Dynamic range: Sample rate = 48 kS/s			92		dBFS	20 Hz - 20 kHz
Total harmonic distortion plus noise	THD + N		-82		dBFS	2, Input = -3 dBFS.
Signal to Noise Ratio	SNR		85		dB	2, 1004 Hz, C-message weighted
Allowable capacitive load to ground	C_L			100	pF	1, At each DAC output.
Power supply rejection ratio	PSRR	50	70		dB	1, 20 Hz - 100 kHz, 100 mVpp supply noise.
Crosstalk			-85	-70	dB	1, Between DAC outputs.

Note 1: Guaranteed by design, not tested in production.
Note 2: Single-ended or differential output.

Figure 30 - THD+N Ratio versus Output Power – Driving Low Impedance

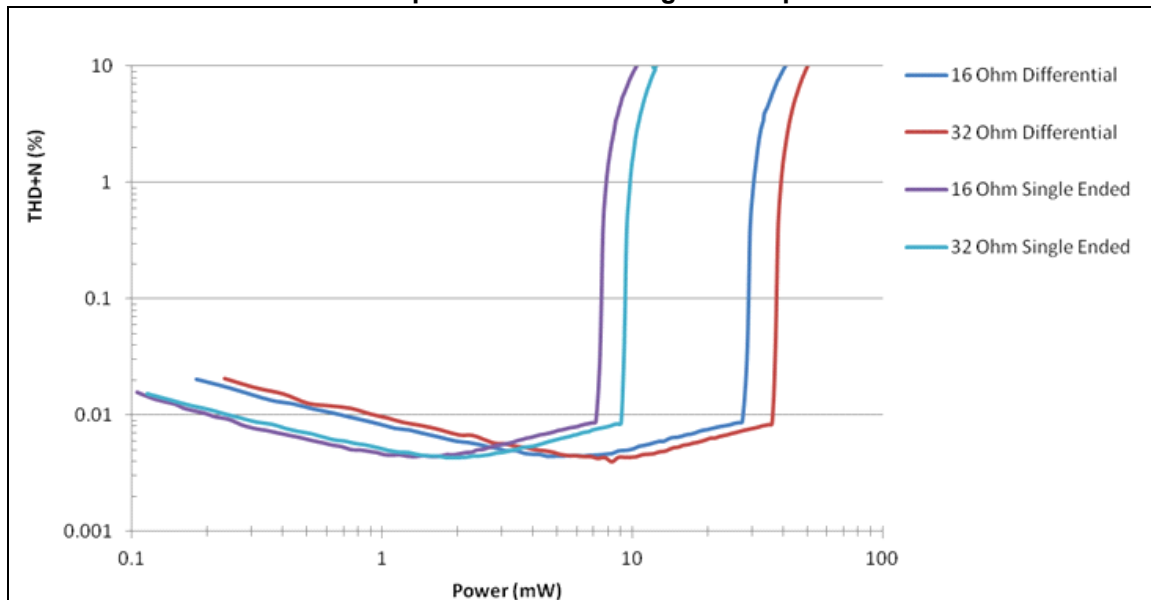
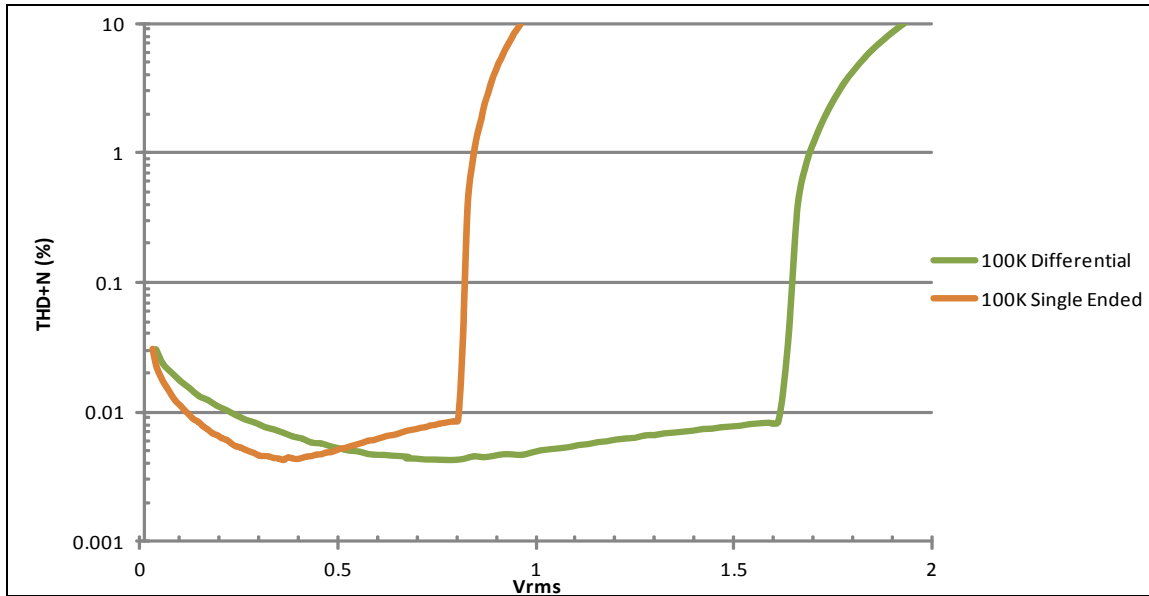


Figure 31 - THD+N Ratio versus V_{RMS} – Driving High Impedance



10.7 External Clock Requirements

In all modes of operation the ZL38052 requires an external clock source. The external clock drives the device’s internal PLL which is the source for the internal timing signals.

The external clock source can be any one of the following:

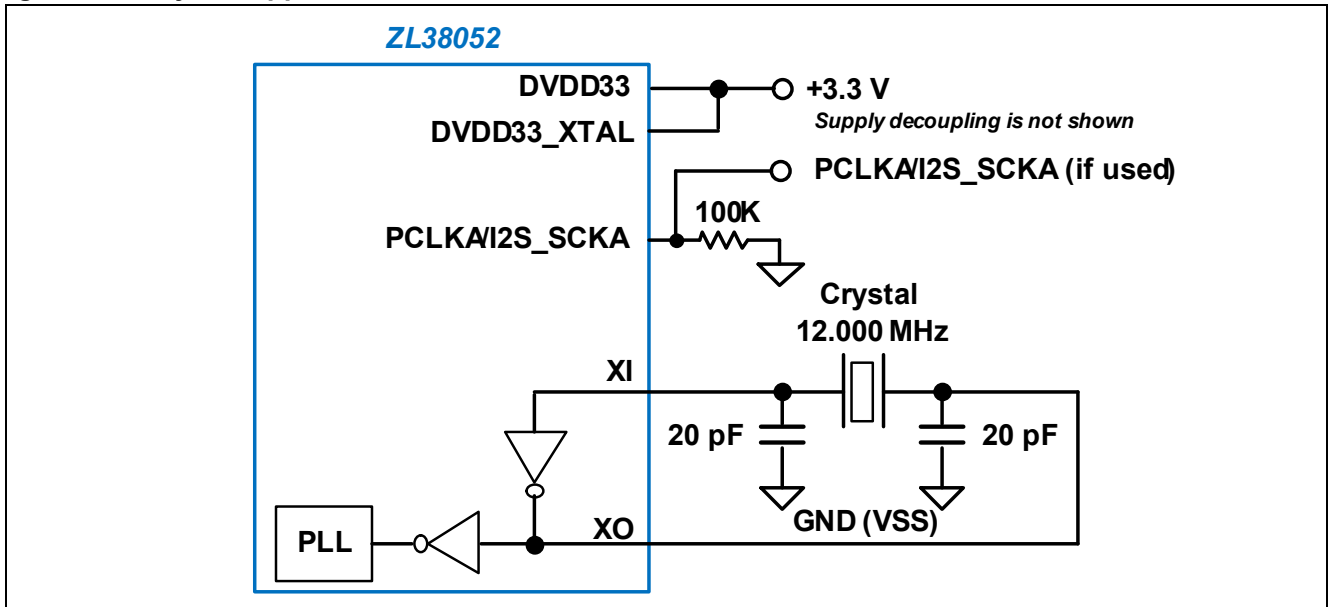
- 12.000 MHz crystal
- 12.000 MHz clock oscillator with a 2.5 V output

The following two sections discuss these options.

10.7.1 Crystal Application

The oscillator circuit that is created across pins XI and XO requires an external fundamental mode crystal that has a specified parallel resonance (f_p) at 12.000 MHz.

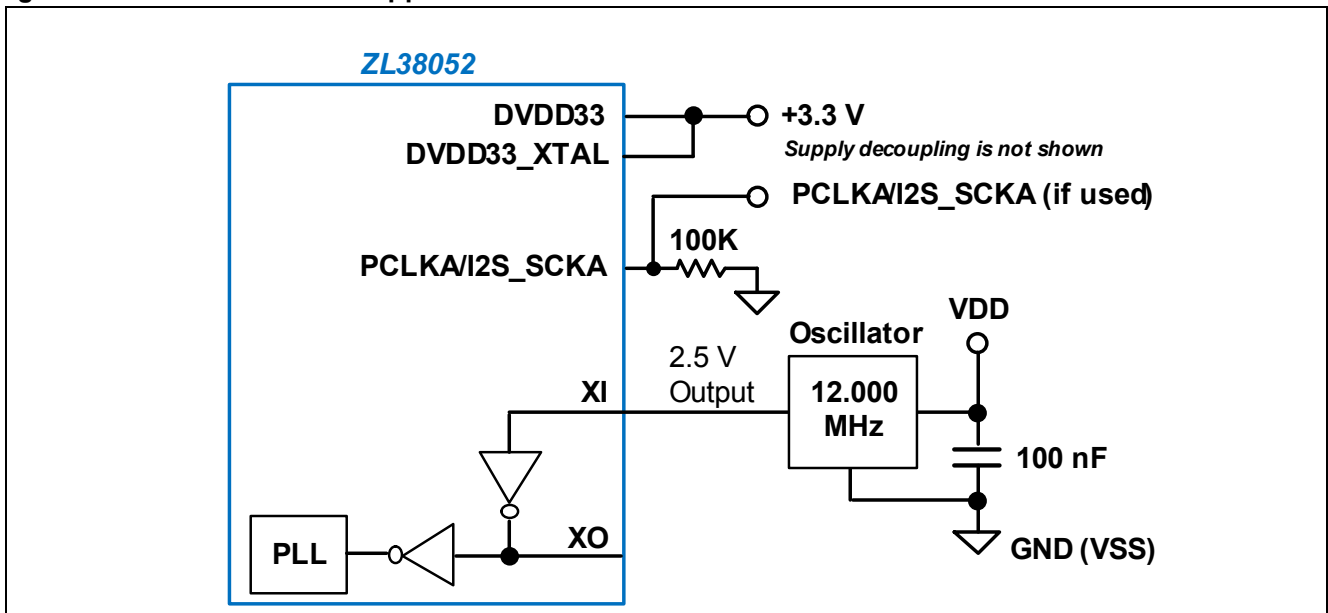
Figure 32 - Crystal Application Circuit



10.7.2 Clock Oscillator Application

[Figure 33](#) illustrates the circuit that is used when the ZL38052 external clock source is a clock oscillator. The oscillator pins are 2.5 V compliant and should not be driven from 3.3 V CMOS without a level shifter or voltage attenuator.

Figure 33 - Clock Oscillator Application Circuit



10.7.3 AC Specifications - External Clocking Requirements

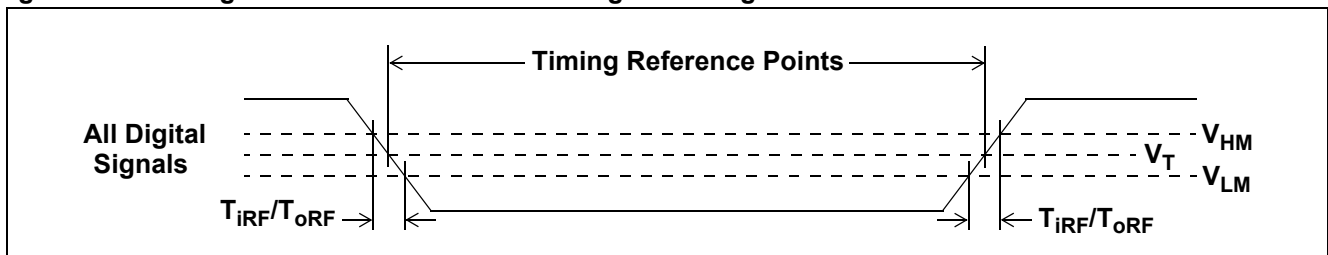
These specifications apply to crystal, clock oscillator, or PCLKA external clocking, unless otherwise specified.

Parameter	Symbol	Min.	Typ.	Max.	Units	Notes / Conditions
External clocking frequency accuracy	A_{OSC}	-50		50	ppm	Not tested in production
External clocking duty cycle	DC_{OSC}	40		60	%	
PCLKA input jitter				1	ns _{pp}	
PCLKA or PCLKB output jitter (master mode)				0.75	ns _{pp}	
PCLKA lock time			200		μs	
Holdover accuracy				50	ppm	Crystal or clock oscillator use only. Not tested in production.

11.0 Timing Characteristics

[Figure 34](#) depicts the timing reference points that apply to the timing diagrams shown in this section. For all timing characteristics, typical values are for $T_A = 25\text{ }^\circ\text{C}$ and nominal supply voltage. Minimum and maximum values are over the industrial $-40\text{ }^\circ\text{C}$ to $85\text{ }^\circ\text{C}$ temperature range and supply voltage ranges as shown in [“Operating Ranges” on page 42](#), except as noted.

Figure 34 - Timing Parameter Measurement Digital Voltage Levels



11.1 TDM Interface Timing Parameters

11.1.1 GCI and PCM Timing Parameters

Specifications for GCI and PCM timing modes are presented in the following table. The specifications apply to both port A and port B in slave operation.

A timing diagram that applies to GCI timing of the TDM interface is illustrated in [Figure 35](#).

Timing diagrams that apply to PCM timing of the TDM interface are illustrated in [Figure 36](#) and [Figure 37](#).

Parameter	Symbol	Min	Typ	Max	Unit	Notes / Conditions
PCLK period	t_{PCY}	122		7812.5	ns	1, 2, 4
PCLK High pulse width	t_{PCH}	48				2
PCLK Low pulse width	t_{PCL}	48				2
Fall time of clock	t_{PCF}			8		
Rise time of clock	t_{PCR}			8		
FS delay (output rising or falling)	t_{FSD}	2		15		2
		2		25		3
FS setup time (input)	t_{FSS}	5				5
FS hold time (input)	t_{FSH}	0.5		$125000 - 2t_{PCY}$		5
Data output delay	t_{DOD}	2		15		2
		2		25		3
Data output delay to High-Z	t_{DOZ}	0		10		6
Data input setup time	t_{DIS}	5				5
Data input hold time	t_{DIH}	0				5
Allowed PCLK jitter time	t_{PCT}			20		Peak-to-peak
Allowed Frame Sync jitter time	t_{FST}			20	Peak-to-peak	

Note 1: PCLK frequency must be within 100 ppm.

Note 2: $C_{LOAD} = 40$ pF

Note 3: $C_{LOAD} = 150$ pF

Note 4: If PCLKA is used to drive the main system clock, it's frequency must be a multiple of 2.048 MHz and it and FSA must be present at all times to maintain proper internal operation.

Note 5: Setup times based on 2 ns PCLK rise and fall times; hold times based on 0 ns PCLK rise and fall times.

Note 6: Guaranteed by design, not tested in production.

Figure 35 - GCI Timing, 8-bit

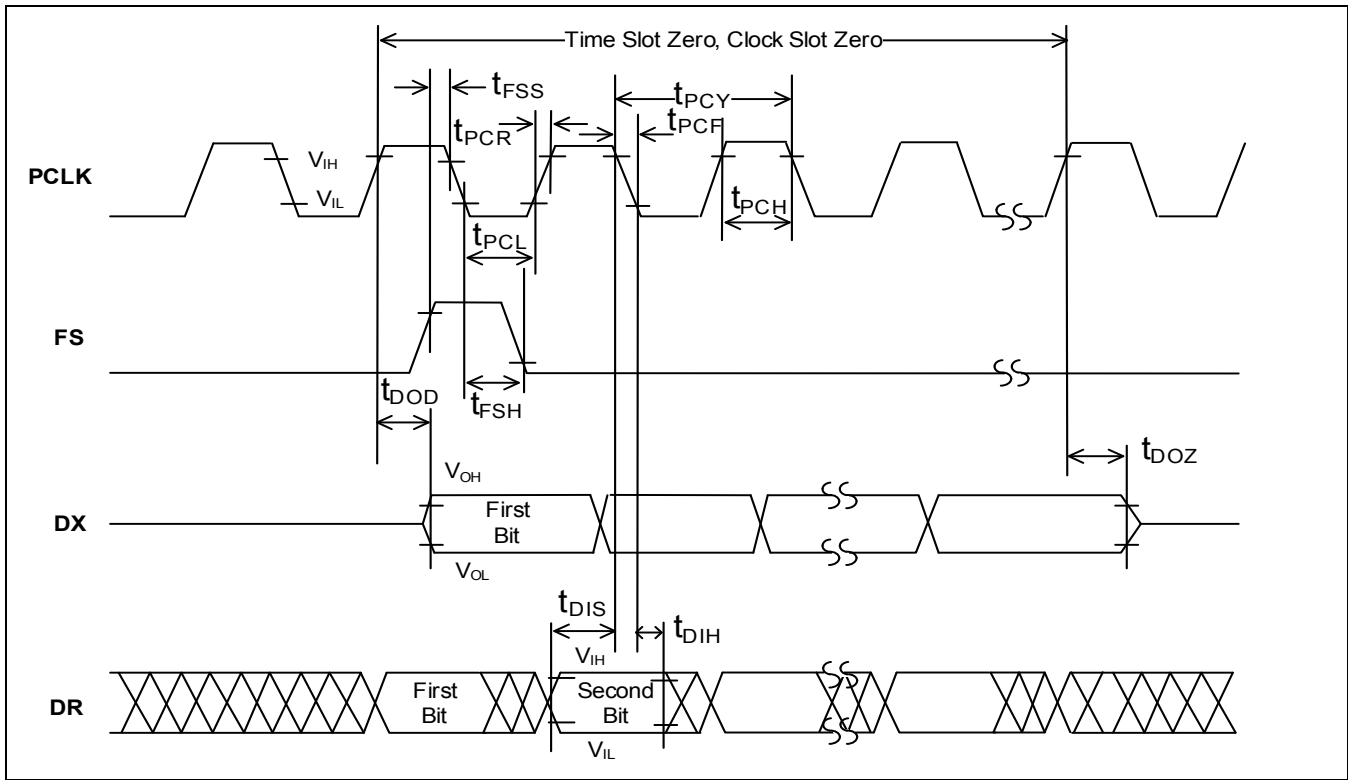


Figure 36 - PCM Timing, 8-bit with xeDX = 0 (Transmit on Negative PCLK Edge)

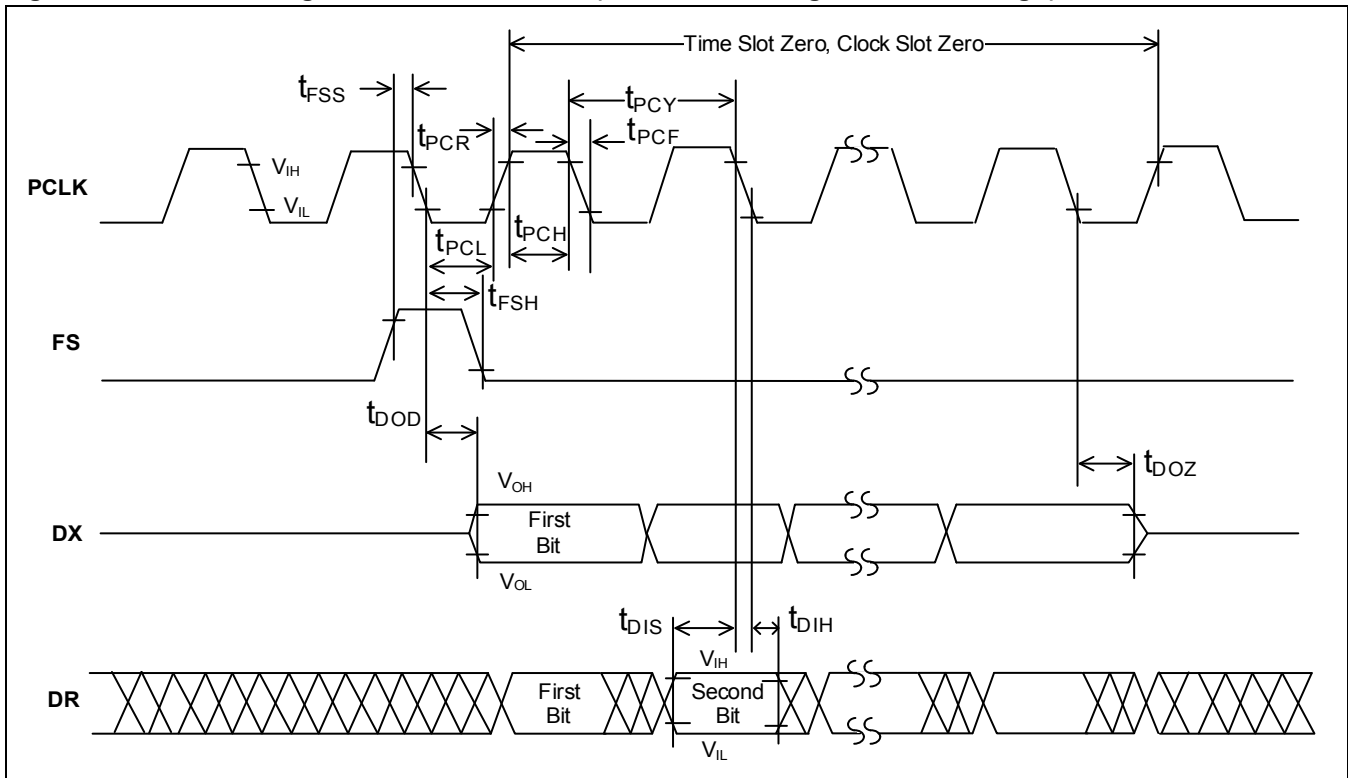
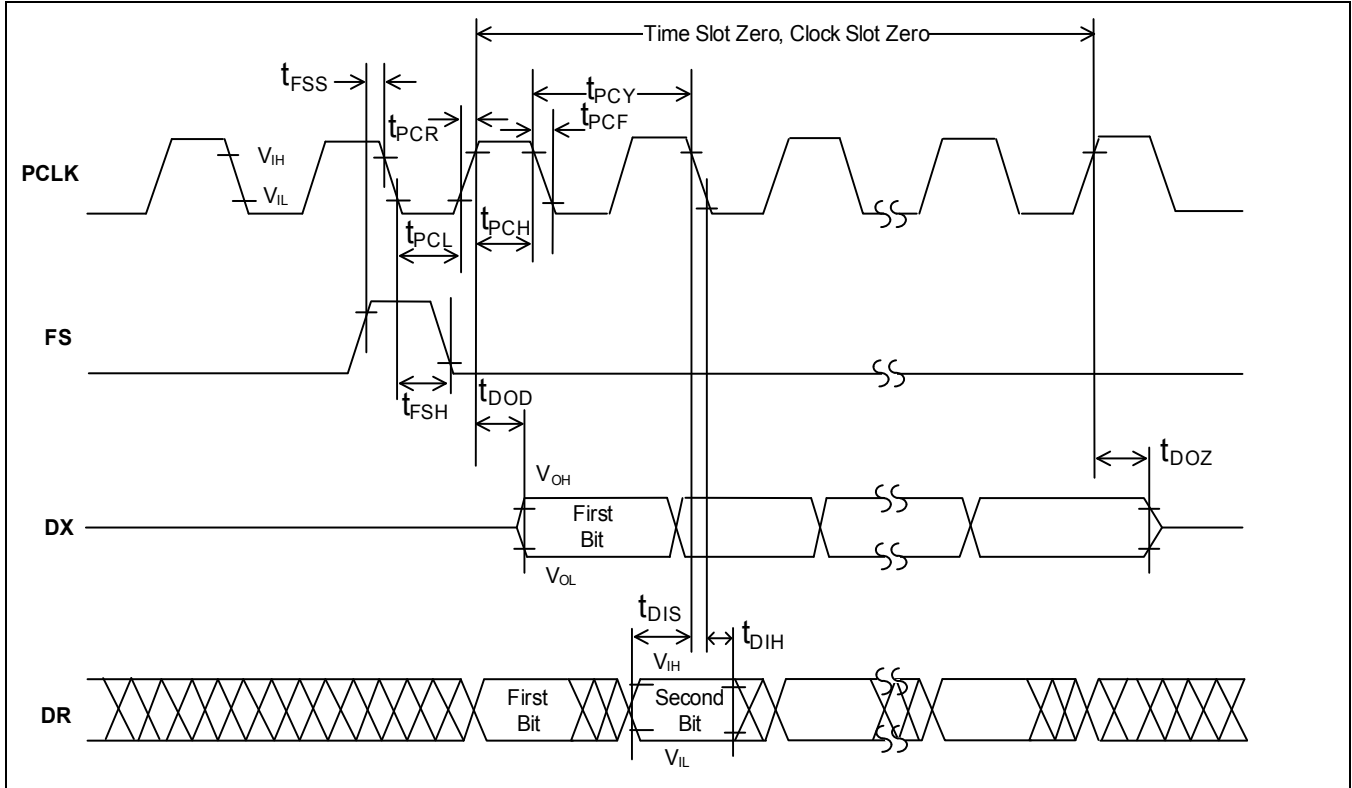


Figure 37 - PCM Timing, 8-bit with xeDX = 1 (Transmit on Positive PCLK Edge)



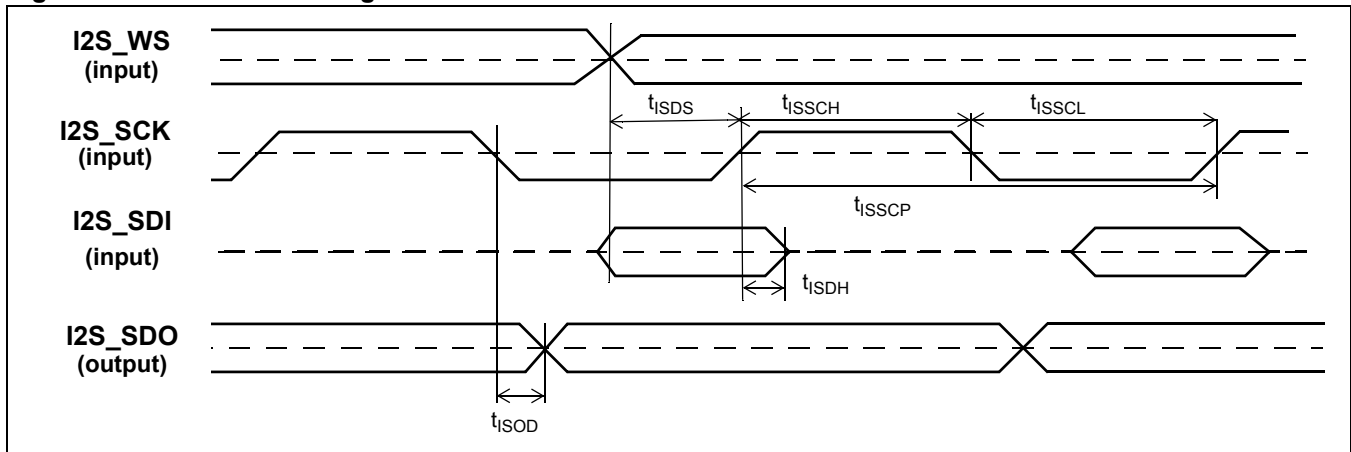
11.1.2 I²S Timing Parameters

11.1.2.1 I²S Slave

Specifications for I²S Slave timing are presented in the following table. The specifications apply to both port A and port B. A timing diagram for the I²S Slave timing parameters is illustrated in [Figure 38](#).

Parameter	Symbol	Min.	Typ.	Max.	Units	Notes / Conditions
I2S_SCK Clock Period $f_s = 48 \text{ kHz}$ $f_s = 8 \text{ kHz}$	t_{ISSCP}		651.04 3.91		ns μs	
I2S_SCK Pulse Width High $f_s = 48 \text{ kHz}$ $f_s = 8 \text{ kHz}$	t_{ISSCH}	292.97 1.76		358.07 2.15	ns μs	
I2S_SCK Pulse Width Low $f_s = 48 \text{ kHz}$ $f_s = 8 \text{ kHz}$	t_{ISSCL}	292.97 1.76		358.07 2.15	ns μs	
I2S_SDI Setup Time	t_{ISDS}	5			ns	
I2S_WS Setup Time	t_{ISDS}	5			ns	
I2S_SDI Hold Time	t_{ISDH}	0			ns	
I2S_WS Hold Time	t_{ISDH}	0.5			ns	
I2S_SCK Falling Edge to I2S_SDO Valid	t_{ISOD}	2		15	ns	$C_{LOAD} = 40 \text{ pF}$

Figure 38 - Slave I²S Timing

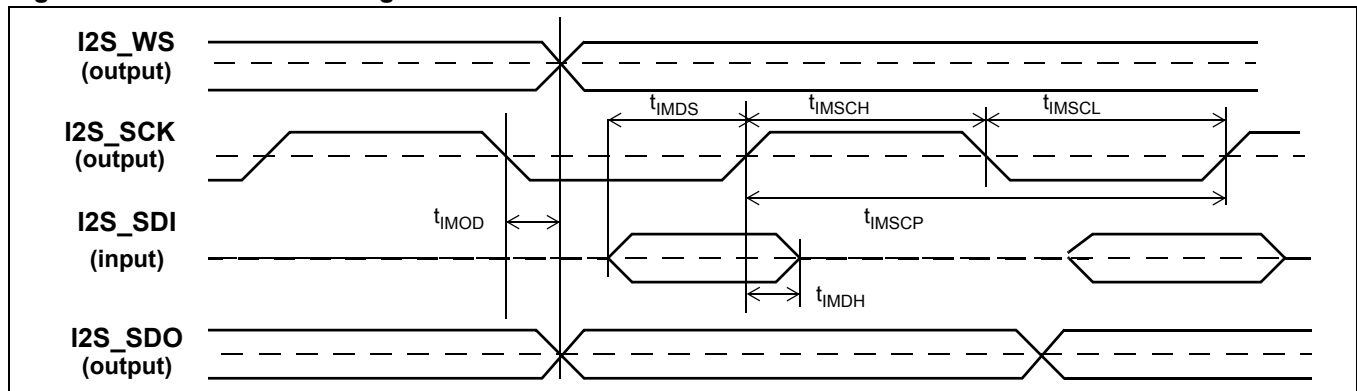


11.1.2.2 I²S Master

Specifications for I²S Slave timing are presented in the following table. The specifications apply to both port A and port B. A timing diagram for the I²S Master timing parameters is illustrated in [Figure 39](#).

Parameter	Symbol	Min.	Typ.	Max.	Units	Notes/Conditions
I2S_SCK Clock Period $f_s = 48 \text{ kHz}$ $f_s = 8 \text{ kHz}$	t_{IMSCP}		651.04 3.91		ns μs	
I2S_SCK Pulse Width High $f_s = 48 \text{ kHz}$ $f_s = 8 \text{ kHz}$	t_{IMSCH}	318.0 1.95		333.0 1.96	ns μs	
I2S_SCK Pulse Width Low $f_s = 48 \text{ kHz}$ $f_s = 8 \text{ kHz}$	t_{IMSCL}	318.0 1.95		333.0 1.96	ns μs	
I2S_SDI Setup Time	t_{IMDS}	5			ns	
I2S_SDI Hold Time	t_{IMDH}	0			ns	
I2S_SCK Falling Edge to I2S_WS	t_{IMOD}	2		15	ns	$C_{LOAD} = 40 \text{ pF}$
I2S_SCK Falling Edge to I2S_SDO Valid	t_{IMOD}	2		15	ns	$C_{LOAD} = 40 \text{ pF}$

Figure 39 - Master I²S Timing



11.2 Host Bus Interface Timing Parameters

The HBI is the main communication port from the host processor to the ZL38052, this port can read and write all of the memory and registers on the ZL38052. The port can be configured as SPI Slave or I²C Slave.

For fastest command and control operation, use the SPI Slave configuration. The SPI Slave can be operated with HCLK speeds up to 25 MHz; the I²C Slave will operate with HCLK speeds up to 400 kHz.

11.2.1 SPI Slave Port Timing Parameters

The following table describes timing specific to the ZL38052 device. A timing diagram for the SPI Slave timing parameters is illustrated in [Figure 40](#).

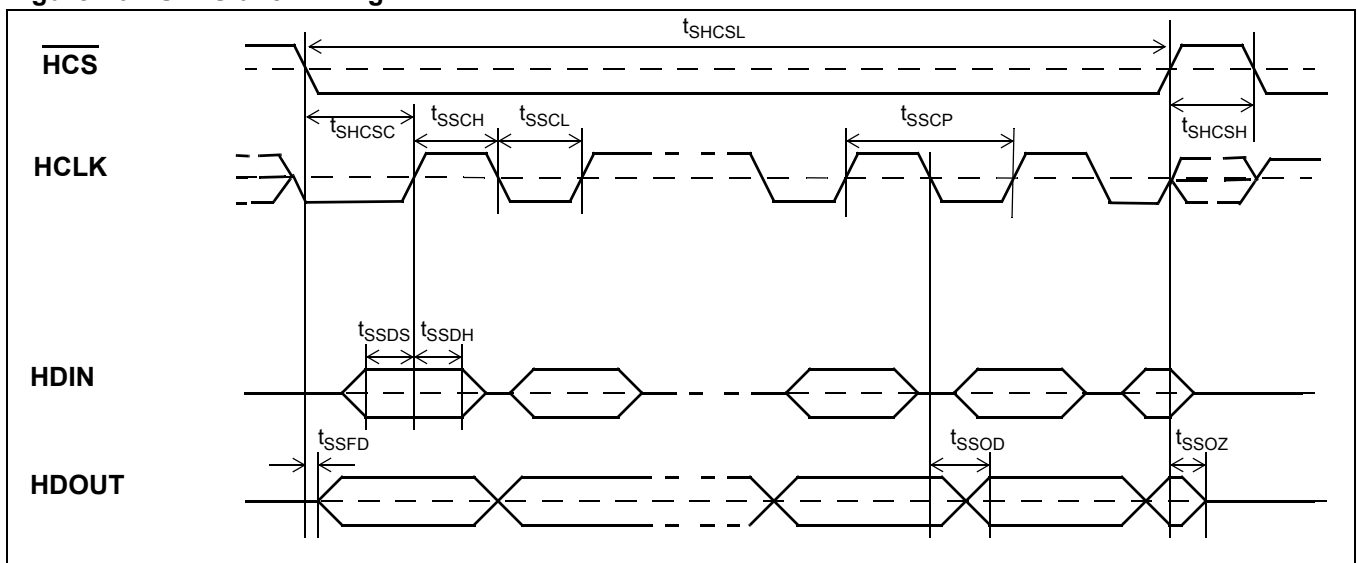
For seamless control operation, both the SPI Slave timing and the system timing need to be considered when operating the SPI Slave at high speeds. System timing includes host set-up and delay times and board delay times.

Parameter	Symbol	Min.	Typ.	Max.	Units	Notes / Conditions
HCLK Clock Period	t_{SSCP}	40			ns	
HCLK Pulse Width High	t_{SSCH}	16	$t_{SSCP}/2$			1
HCLK Pulse Width Low	t_{SSCL}	16	$t_{SSCP}/2$			1
HDIN Setup Time	t_{SSDS}	5				
HDIN Hold Time	t_{SSDH}	0				
\overline{HCS} Asserted to HCLK Rising Edge: Write Read if host samples on falling edge Read if host samples on rising edge	t_{SHCSC}	5 5 $t_{SSFD} + \text{host HDOUT setup time to HCLK}$	$t_{SSCP}/2$ $t_{SSCP}/2$ $t_{SSFD} + t_{SSCP}/2$			
HCLK Driving Edge to HDOUT Valid	t_{SSOD}	2		15		$C_{LOAD} = 40 \text{ pF}$
\overline{HCS} Falling Edge to HDOUT Valid	t_{SSFD}	0		15		2, $C_{LOAD} = 40 \text{ pF}$
\overline{HCS} De-asserted to HDOUT Tristate	t_{SSOZ}	0		10		5, $C_{LOAD} = 40 \text{ pF}$
\overline{HCS} Pulse High	t_{SHCSH}	20	$t_{SSCP}/2$			1, 3
\overline{HCS} Pulse low	t_{SHCSL}				4	

- Note 1: HCLK may be stopped in the high or low state indefinitely without loss of information. When \overline{HCS} is at low state, every 16 HCLK cycles, the 16-bit received data will be interpreted by the SPI interface logic.
- Note 2: The first data bit is enabled on the falling edge of \overline{HCS} or on the falling edge of HCLK, whichever occurs last.
- Note 3: The SPI Slave requires 61ns \overline{HCS} off time just to make the transition of \overline{HCS} synchronized with HCLK clock. In the command framing mode, there is no \overline{HCS} off time between each 16-bit command/data, and \overline{HCS} is held low until the end of command.
- Note 4: If \overline{HCS} is not held low for 8 or 16 HCLK cycles exactly, the SPI Slave will reset. During byte or word framing mode, \overline{HCS} is held low for the whole duration of the command. Multiple commands can be transferred with \overline{HCS} low for the whole duration of the multiple commands. The rising edge of the \overline{HCS} indicates the end of the command sequence and resets the SPI Slave.

Guaranteed by design, not tested in production.

Figure 40 - SPI Slave Timing



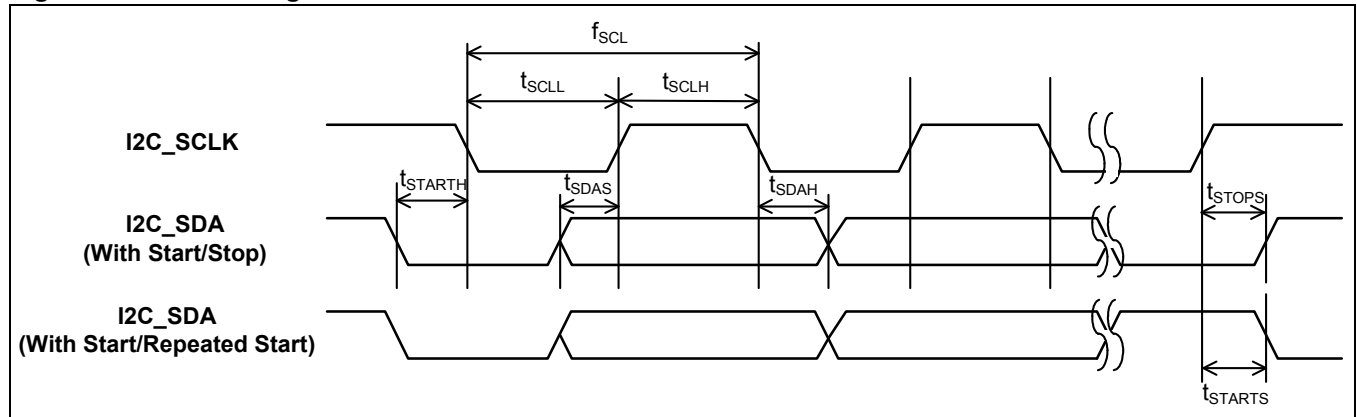
11.2.2 I²C Slave Interface Timing Parameters

The I²C interface uses the SPI Slave interface pins.

Specifications for I²C interface timing are presented in the following table. A timing diagram for the I²C timing parameters is illustrated in [Figure 41](#).

Parameter	Symbol	Min.	Typ.	Max.	Units	Notes / Conditions
SCLK Clock Frequency	f_{SCL}	0		400	kHz	
START Condition Hold Time	t_{STARTh}	0.6			μ s	
SDA data setup time	t_{SDAS}	100			ns	
SDA Hold Time Input	t_{SDAH}	100			ns	
SDA Hold Time Output	t_{SDAH}	300			ns	
High period of SCLK	t_{SCLH}	0.6			μ s	
Low period of SCLK	t_{SCLL}	1.3			μ s	
STOP Condition Setup Time	t_{STOPS}	0.6			μ s	
Repeated Start Condition Setup Time	t_{STARTS}	0.6			μ s	
Pulse Width Spike Suppression, glitches ignored by input filter	t_{SP}	50			ns	

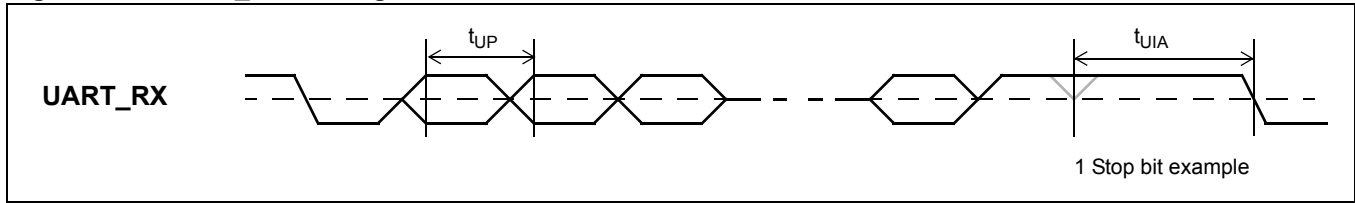
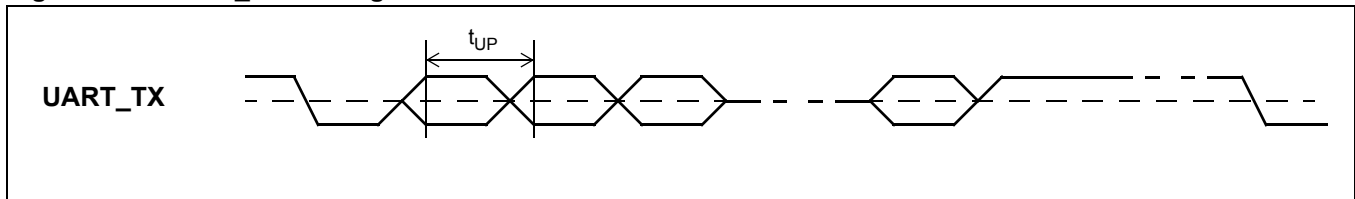
Figure 41 - I²C Timing Parameter Definitions



11.3 UART Timing Parameters

Specifications for UART timing are presented in the following table. Timing diagrams for the UART timing parameters are illustrated in [Figure 42](#) and [Figure 43](#).

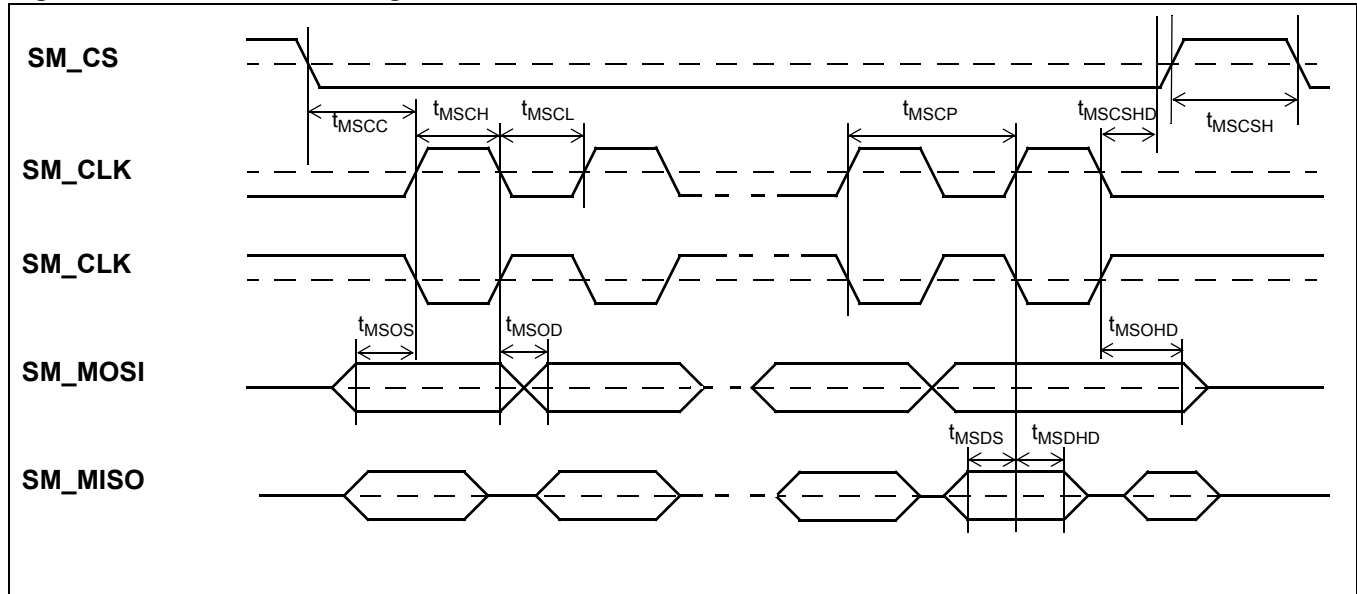
Parameter	Symbol	Min.	Typ.	Max.	Units	Notes / Conditions
UART_RX and UART_TX bit width Baud rate = 115.2 kbps	t_{UP}		8.68		μ s	
Allowed baud rate deviation 8 bits with no parity				4.86	%	Guaranteed by design, not tested in production.

Figure 42 - UART_RX Timing

Figure 43 - UART_TX Timing


11.4 Master SPI Timing Parameters

Specifications for Master SPI timing are presented in the following table. A timing diagram for the Master SPI timing parameters is illustrated in [Figure 44](#).

Parameter	Symbol	Min.	Typ.	Max.	Units	Notes/Conditions
SM_CLK Clock Period	t_{MSCP}	40		320	ns	Max. 25.0 MHz
SM_CLK Pulse Width High	t_{MSCH}	$(t_{MSCP}/2) - 2$		160		
SM_CLK Pulse Width Low	t_{MSCL}	$(t_{MSCP}/2) - 2$		160		
SM_MISO Setup Time	t_{MSDS}	3				
SM_MISO Hold Time	t_{MSDHD}	0				
SM_CS Asserted to SM_CLK Sampling Edge	t_{MSCC}	$(t_{MSCP}/2) - 4$				
SM_CLK Driving Edge to SM_MOSI Valid	t_{MSOD}	-1		2		$C_{LOAD} = 40 \text{ pF}$
SM_MOSI Setup to SM_CLK Sampling Edge	t_{MSOS}	$(t_{MSCP}/2) - 4$				$C_{LOAD} = 40 \text{ pF}$
SM_MOSI Hold Time to SM_CLK Sampling Edge	t_{MSOHD}	$(t_{MSCP}/2) - 4$				$C_{LOAD} = 40 \text{ pF}$
SM_CS Hold Time after last SM_CLK Sampling Edge	t_{MSCSHD}	$(t_{MSCP}/2) - 4$				
SM_CS Pulse High	t_{MSCSH}	$(t_{MSCP}/2) - 2$				

Figure 44 - Master SPI Timing


12.0 AEC Tuning

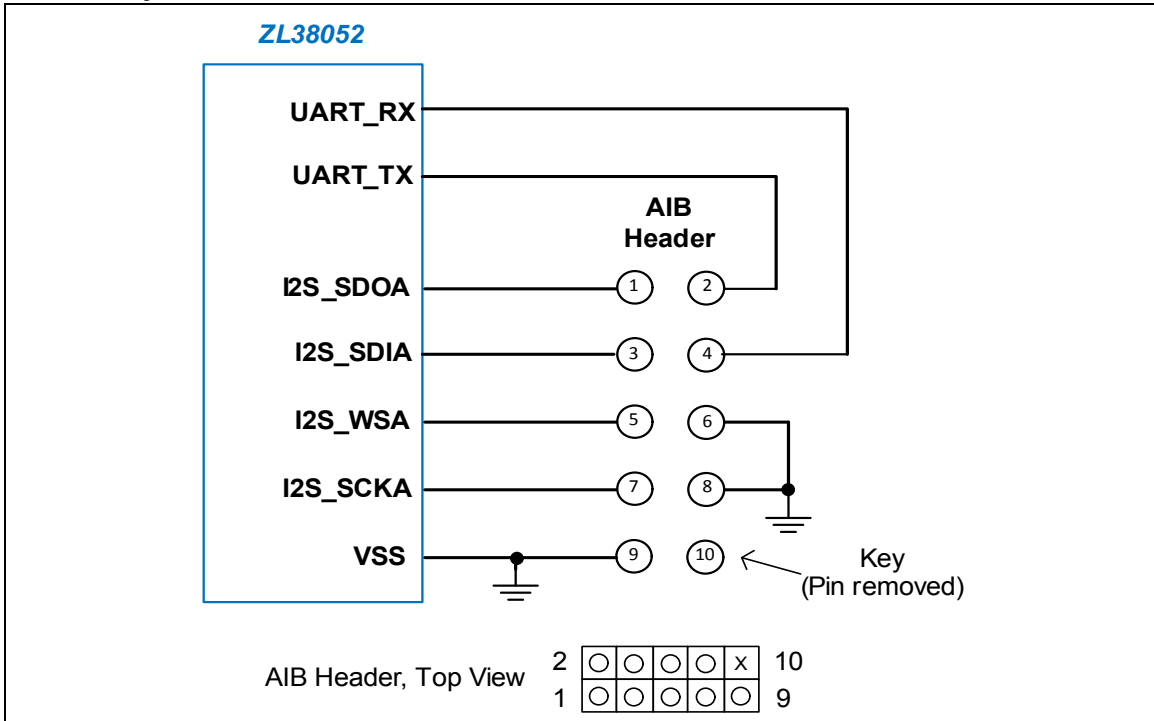
To optimize the acoustic properties of a given system design, the Audio Processor firmware requires gain and level tuning. The mechanical design, including the speaker and microphone quality and placement, will all affect the system's acoustic performance. Microsemi has developed *MiTuner*[™] GUI Software (ZLS38508) and the Microsemi Audio Interface Box (AIB) Evaluation Kit (ZLE38470BADA) to automatically optimize the firmware's tunable parameters for a given hardware design, facilitating the system design process and eliminating the need for tedious manual tuning. In order to achieve a high level of acoustic performance for a given enclosure, the *MiTuner* GUI Software performs both Auto Tuning and Subjective Tuning.

Access to the UART and the TDM-A port of the ZL38052 need to be provided on the system board in order to perform Auto Tuning or Subjective Tuning with the ZLS38508 software. [Figure 45](#) shows the nodes that need to be made available and illustrates an AIB Header that when mounted, will provide a direct connection to the Audio Interface Box cable (no soldering or jumpers required). The header only needs to be populated on the system board(s) that are used for tuning evaluation.

Note: Any connections to a host processor need to be isolated from the UART and I²S ports during the tuning process. If a host processor is connected to these ports, a resistor should be placed between the host and each ZL38052 port signal, so that the resistor can be removed to isolate the host from the ZL38052 without interfering with the ZL38052's connection to the AIB.

To interface between the header and the AIB, a 10-wire ribbon cable is used. The cable is terminated on both ends with a double row, 5 position, 100 mil (2.54 mm) female socket strip. Pin 10 on each socket is keyed to ensure proper signal connection. On the system board header pin 10 must be removed, or alternatively both pins 9 and 10 can be eliminated to reduce the space needed on the system board. Signal integrity series termination resistors are provided for the interface in the AIB.

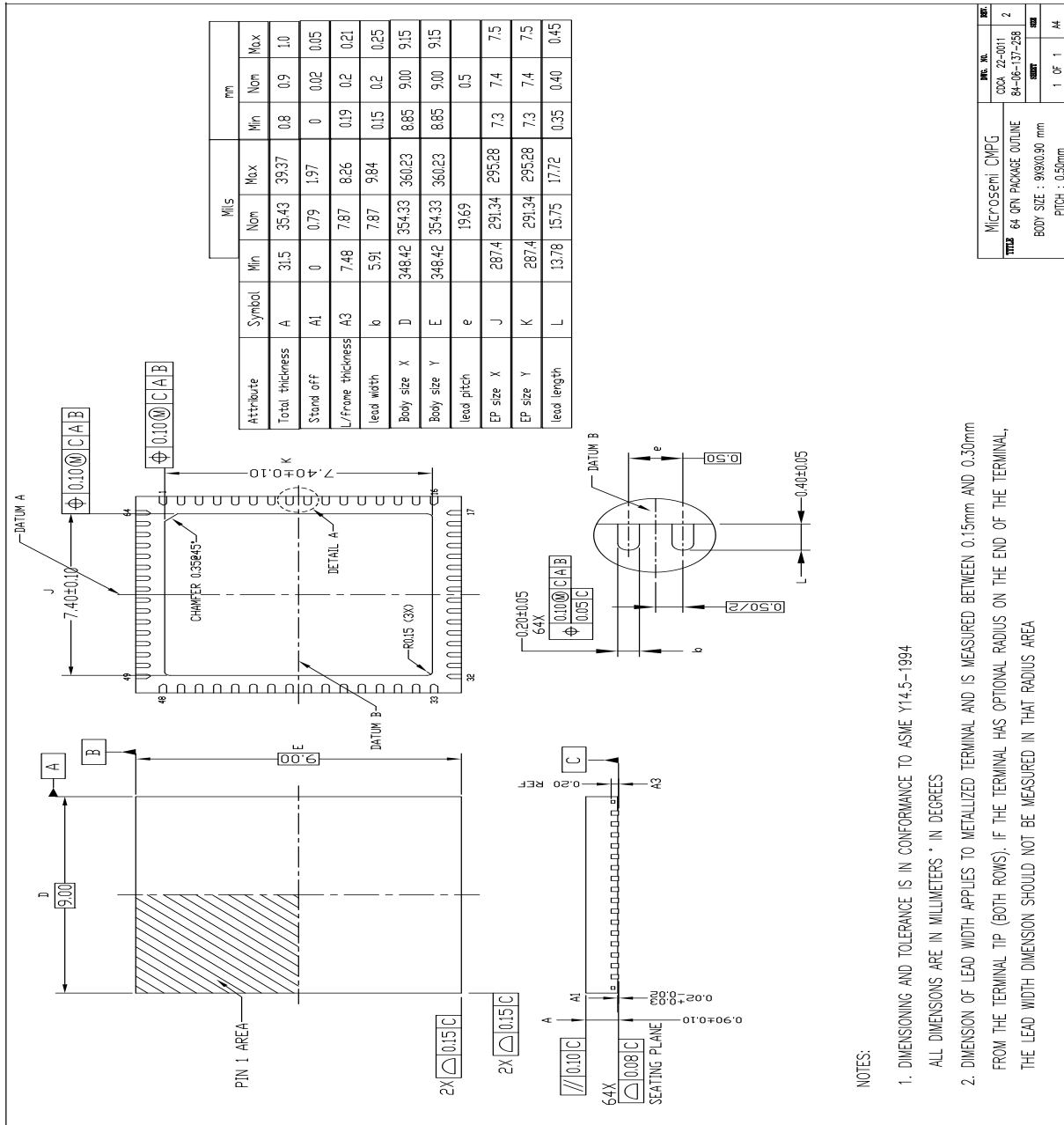
Figure 45 - AIB System Board Connection



Note: A Samtec TSW-105-07-L-D through-hole terminal strip, or a Samtec TSM-105-01-L-DV surface mount terminal strip, or a suitable equivalent can be used for the AIB Header. The header is a double row, 5 position, 10-pin male 100 mil (2.54 mm) unshrouded terminal strip with 25 mil (0.64 mm) square vertical posts that are 230 mils (5.84 mm) in length.

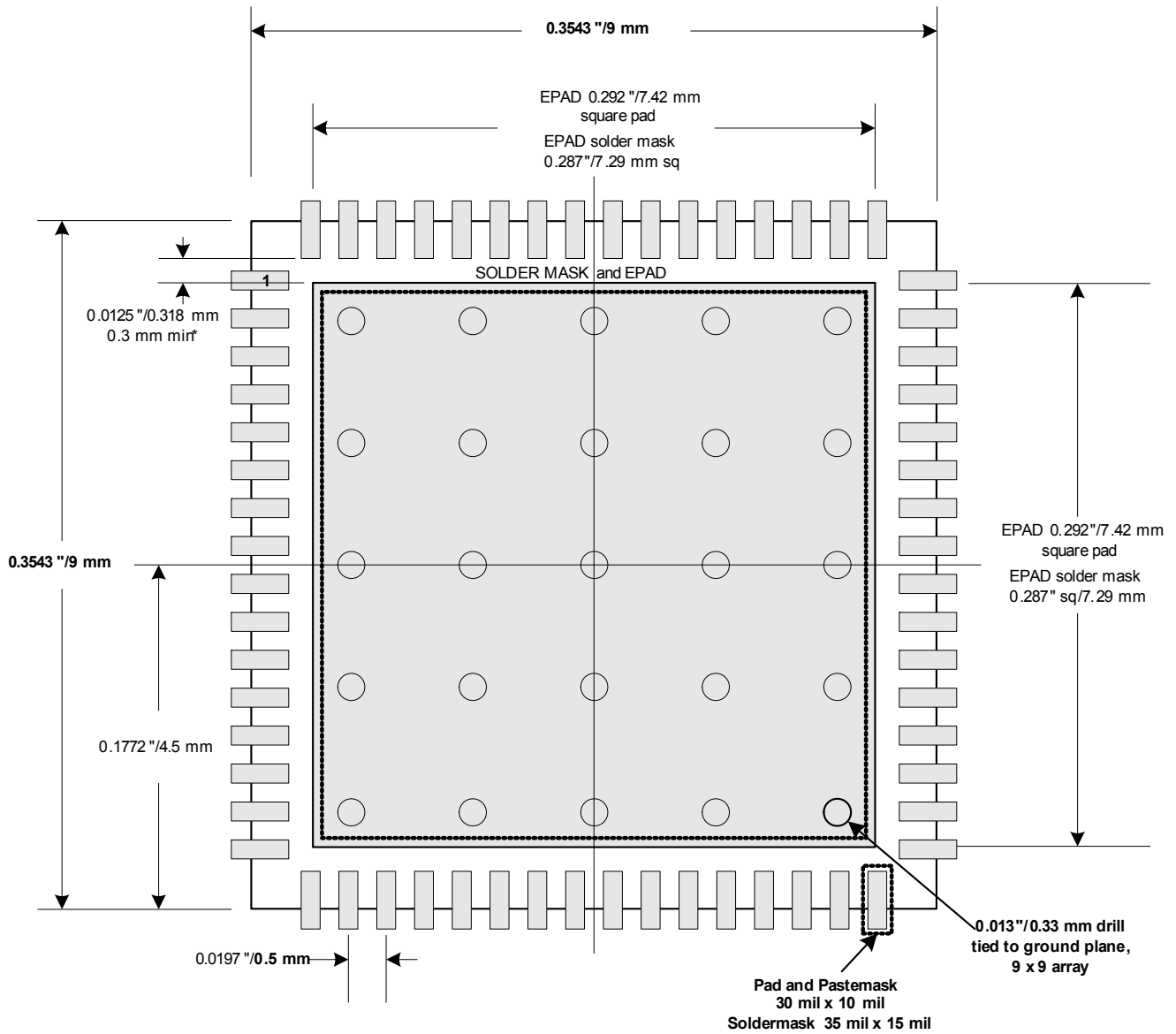
13.0 Package Outline Drawings

Figure 46 - 64-Pin QFN



Microsemi CMPG	REV. NO.	REV.
64 QFN PACKAGE OUTLINE	COX 22-0011	2
BODY SIZE : 9x9x0.90 mm	84-06-137-258	
PITCH : 0.50mm	DATE	
	1 OF 1	AT

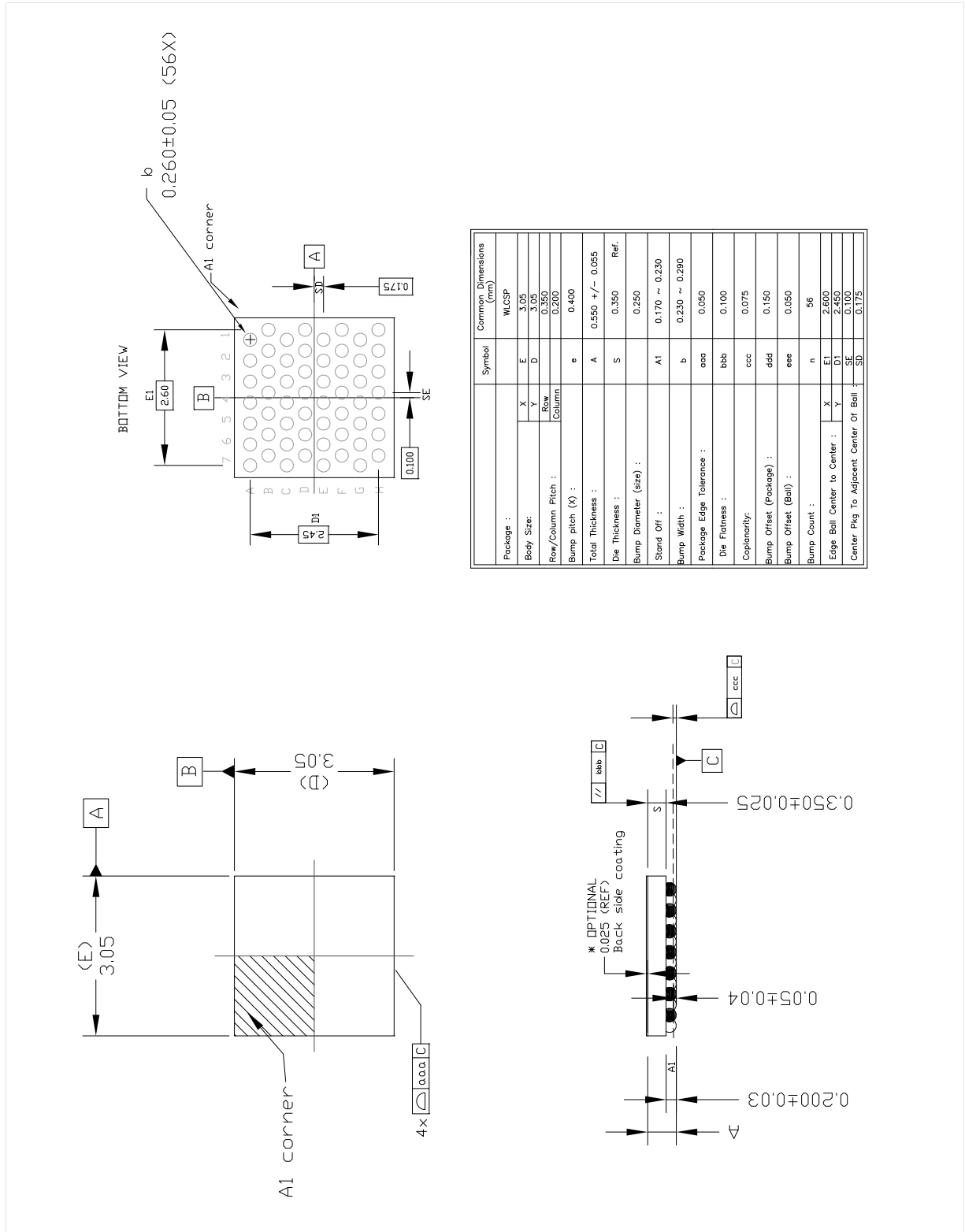
Figure 47 - Recommended 64-Pin QFN Land Pattern – Top View



**64-QFN
9 mm x 9 mm, 0.5 mm pitch**

* Minimum spacing between pins and epad must be 0.3 mm
EPAD configuration uses 0.292"/7.42 mm square pad tied to a ground plane with a 5 x 5 array of 0.013"/0.33 mm vias.

Figure 48 - 56-Ball WLCSP



Symbol	Common Dimensions (mm)
Package :	WLCSP
Body Size :	3.05
X :	3.05
Y :	3.05
Row/Column Pitch :	0.260
Row :	7
Column :	8
Bump pitch (X) :	e
e :	0.400
Total Thickness :	A
A :	0.550 +/- 0.055
Die Thickness :	S
S :	0.350 Ref.
Bump Diameter (size) :	
Bump Diameter (size) :	0.250
Stand Off :	A1
A1 :	0.170 ~ 0.230
Bump Width :	b
b :	0.230 ~ 0.290
Package Edge Tolerance :	aaa
aaa :	0.050
Die Flatness :	bbb
bbb :	0.100
Coplanarity :	ccc
ccc :	0.075
Bump Offset (Package) :	ddd
ddd :	0.150
Bump Offset (Ball) :	eee
eee :	0.050
Bump Count :	n
n :	56
Edge Ball Center to Center :	X
X :	2.600
Center Pig To Adjacent Center Of Ball :	Y
Y :	2.450
Z :	0.175
SE :	0.100
SD :	0.175

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